UIDE

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ING. MECATRÓNICA

Thesis prior to obtaining the degree of Mechatronics Engineer.

AUTHOR: Martín Felipe Tobar Flores

TUTOR: Ing. Gabriela Andaluz, MSc.

ANEXOS

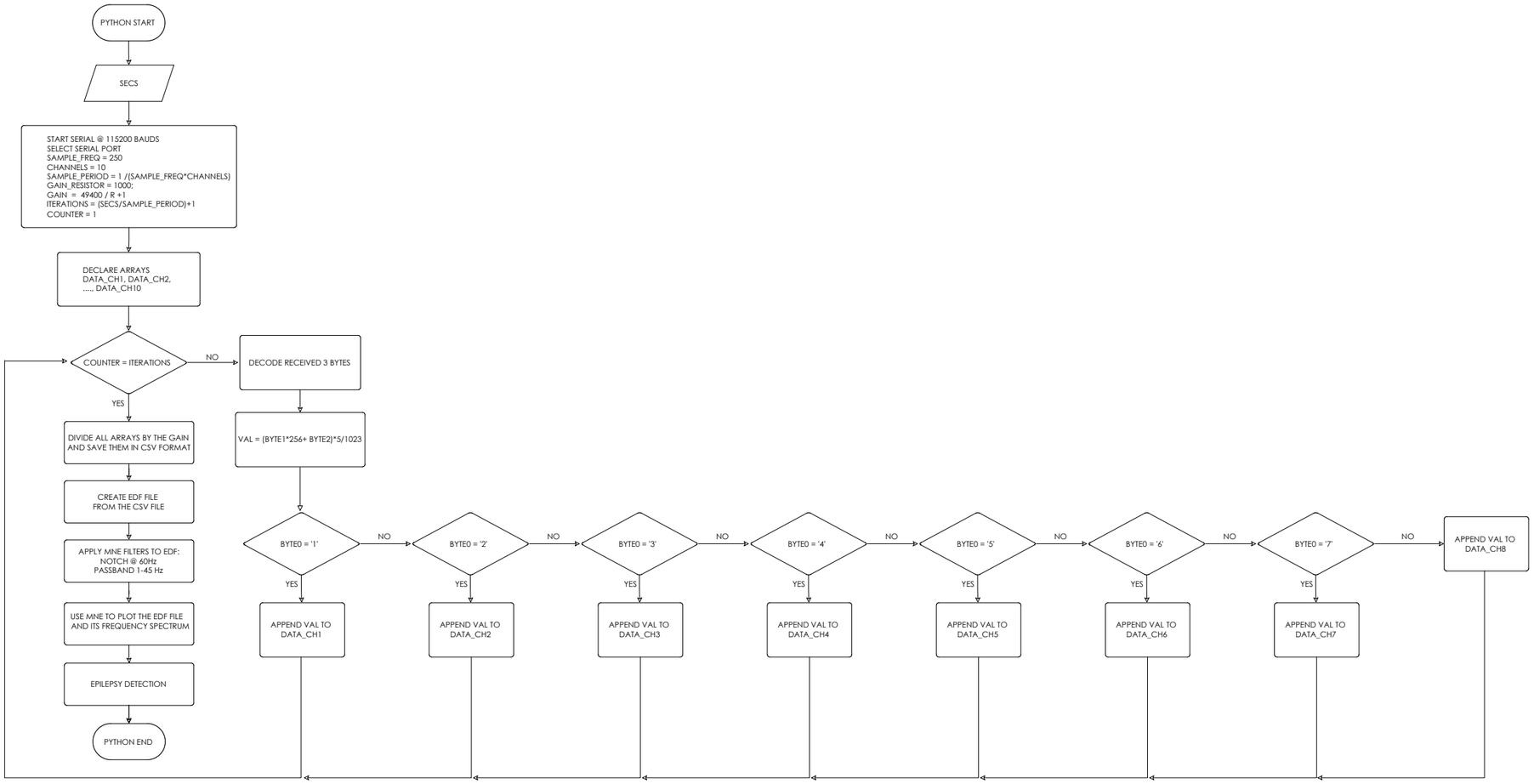
Design and Implementation of an Electroencephalograph Prototype for the Acquisition and Visualization of Brain Signals which by Means of Neural Networks allows the Detection of an Anomaly.

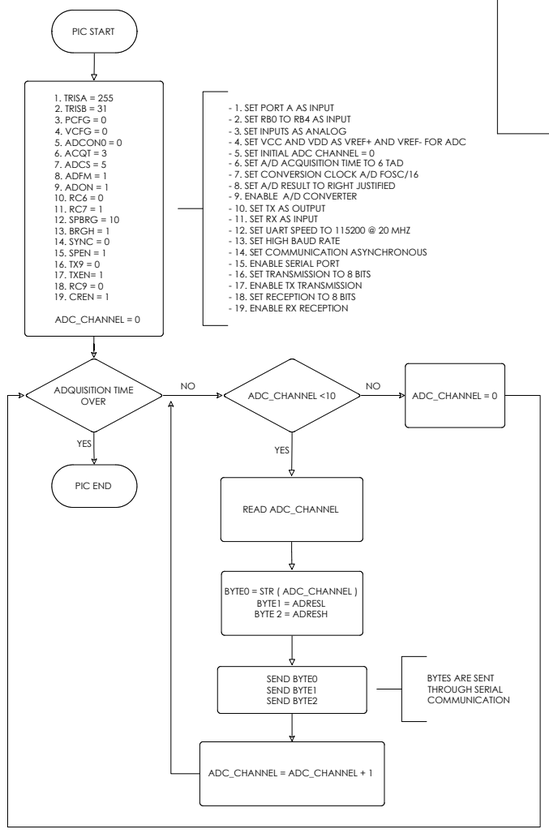
QUITO – ECUADOR | 2023

List of Appendices

Appendix A

Informatics Diagrams





NOTE:
PYTHON START MEANS IS THE START OF THE PYTHON ALGORITHM IN THE LAPTOP SIDE
PIC START MEANS IS THE START OF THE PIC ALGORITHM OF THE PIC MICROCONTROLLER

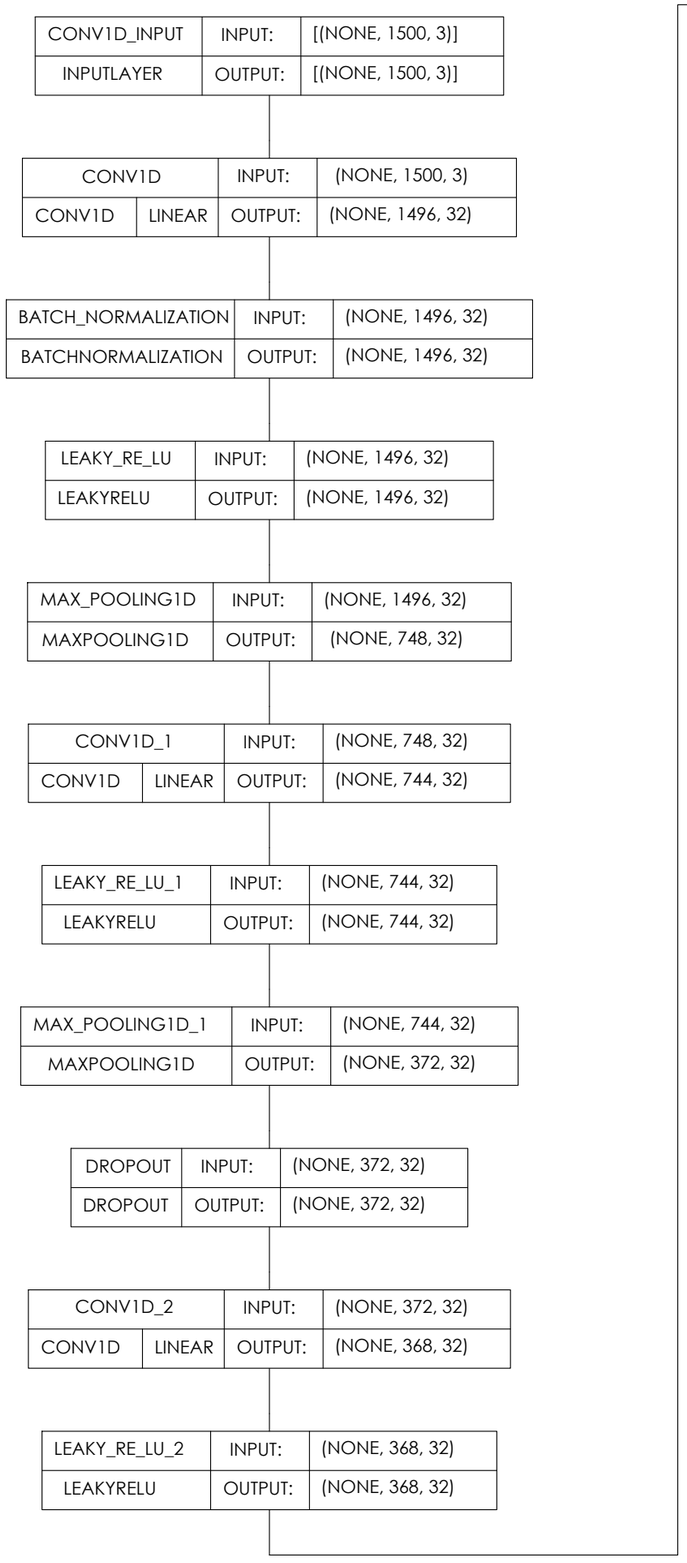
UIDE	MECHATRONICS ENGINEERING	DWN.	TOBAR M.	12/29/22
		DES.	TOBAR M.	11/01/22
		RWD.	ANDALUZ G.	01/05/23

EEG SYSTEM THAT CAPTURES BRAIN WAVES, DISPLAYS THEM AND DETECTS EPILEPSY PATRONS

D01 - 001

N/A

N/A



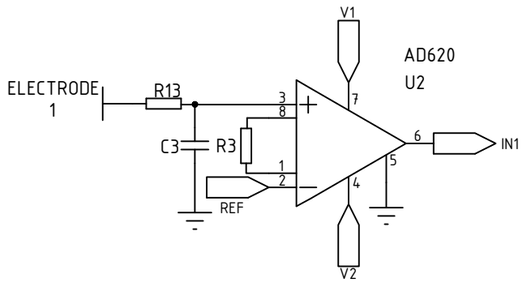
NOTES: ALL FILTERS = 10; ALL KERNELS SIZE = 5.

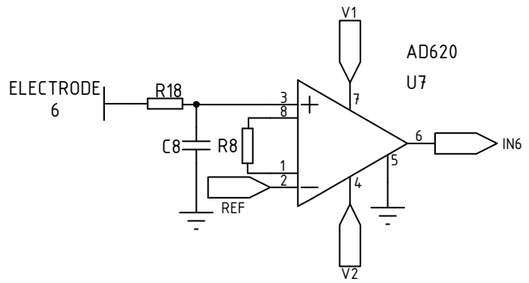
UIDE	MECHATRONICS ENGINEERING	DWN.	TOBAR M.	12/29/22
		DES.	TOBAR M.	11/01/22
		RWD.	ANDALUZ G.	01/05/23

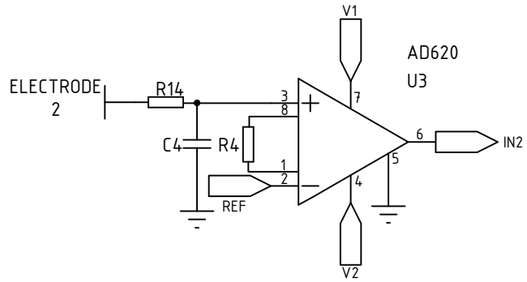
CONVOLUTIONAL NEURAL NETWORK	D01 - 002	N/A
		N/A

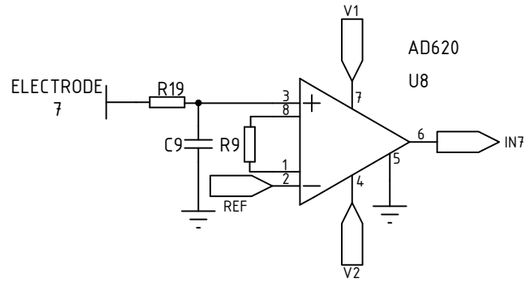
Appendix B

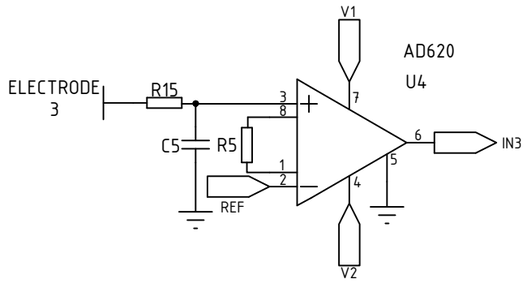
Electronic Diagrams

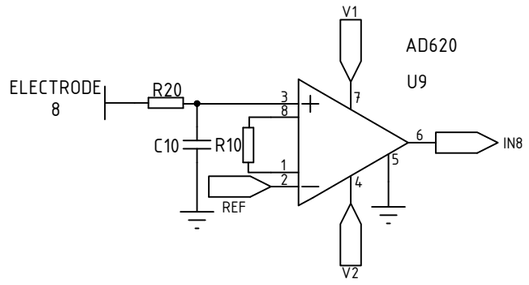


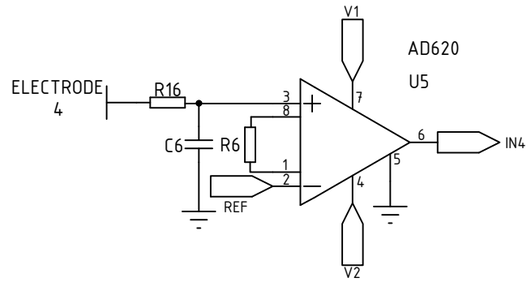


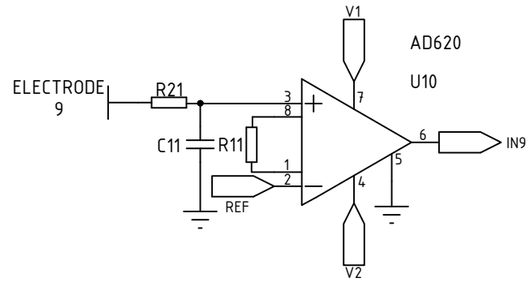


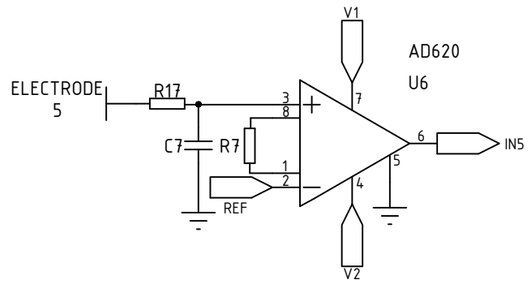


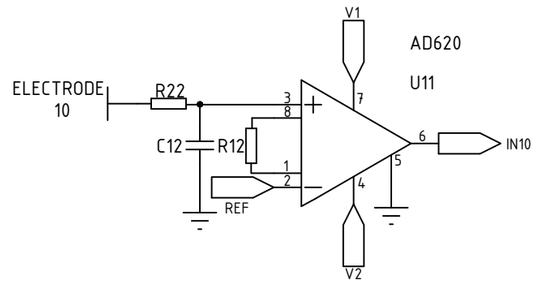


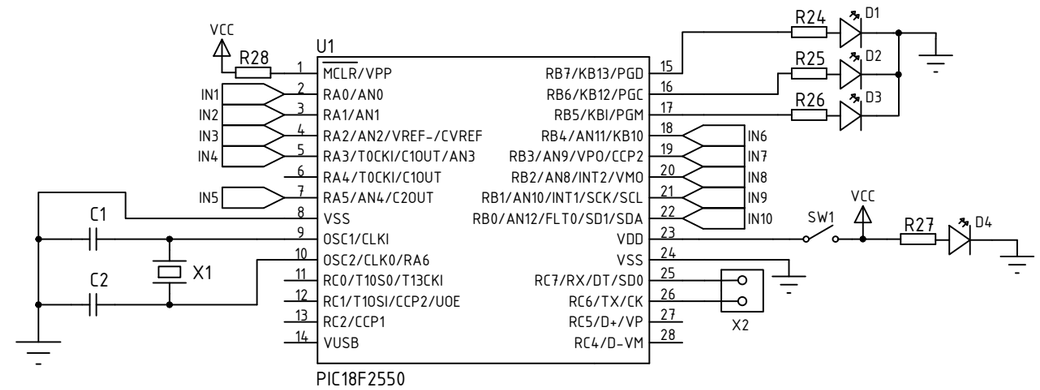


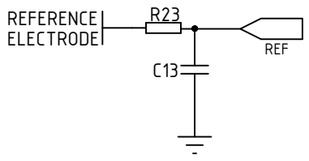


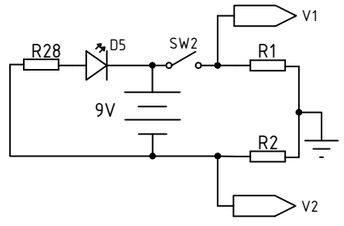












POWER SUPPLY	
VCC	5 VDC
GND	0 VDC

UIDE	MECHATRONICS ENGINEERING	DWN.	TOBAR M.	12/29/22
		DES.	TOBAR M.	11/01/22
		RWD.	ANDALUZ G.	01/05/23

EEG SYSTEM THAT CAPTURES BRAIN WAVES, DISPLAYS THEM AND DETECTS EPILEPSY

ELECTRONIC PLAN

D02 - 001

N/A

N/A

POS.	DESCRIPTION	QTY.	OBSERVATIONS
	CAPACITORS		
C1,C2	22pf CERAMIC 10V	2	CRYSTALL CAPACITORS
C3 - C13	100uF ELECTROLYTIC 10V	11	48 Hz HIGH PASS FILTER CAPACITORS
	DIODES		
D1 - D5	GREEN LEDs 20mA 5V	5	STATUS INDICATOR LEDs
	RESISTORS		
R1, R2, R28	1k Ω $\frac{1}{4}$ W	3	
R3-R12	1k Ω $\frac{1}{4}$ W	10	AD620 GAIN RESISTOR
R13-R23	33 Ω $\frac{1}{4}$ W	11	48 Hz HIGH PASS FILTER RESISTORS
R24-R28	220 Ω $\frac{1}{4}$ W	5	INDICATOR LEDs RESISTORS
	SWITCHES		
SW1, SW2	N.O. SWITCH 1A 5V SIMPLE CONTACT	2	
	INTEGRATED CIRCUITS		
U1	PIC 18F2550	1	
U3-U11	AD620 INSTRUMENTAL AMPLIFIER	10	EEG SIGNAL AMPLIFICATION
	MISCELLANEOUS		
X1	20 MHz CRYSTALL	1	
X2	TERMINAL BLOCK 1A 5V	1	RX AND TX CONNECTORS

UIDE MECHATRONICS ENGINEERING

DIB.	TOBAR M.	01/11/22
DIS.	TOBAR M.	16/11/22
REV.	ANDALUZ G.	16/11/22

10-CHANNEL ELECTROENCEPHALOGRAPH

COMPONENTS LIST

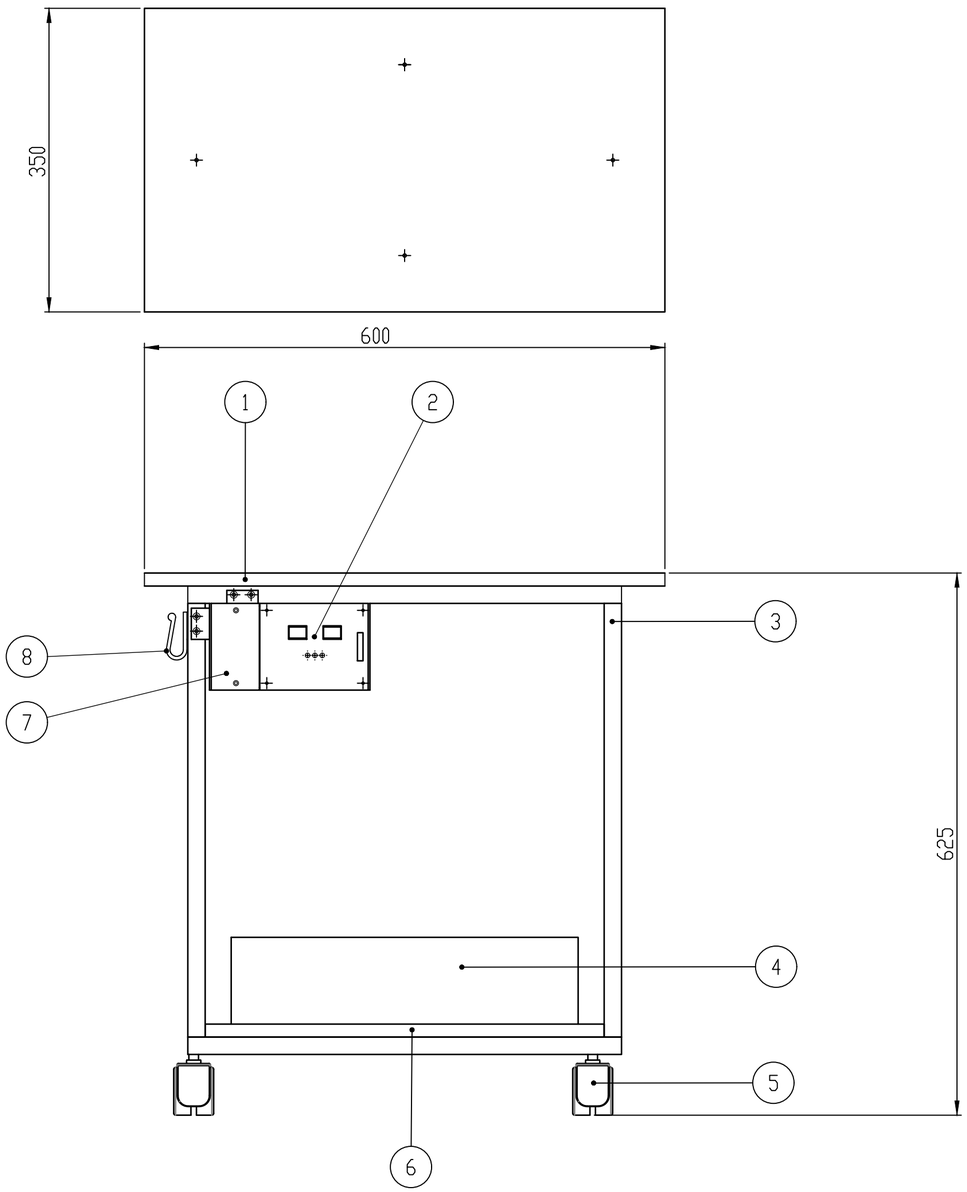
D02-101

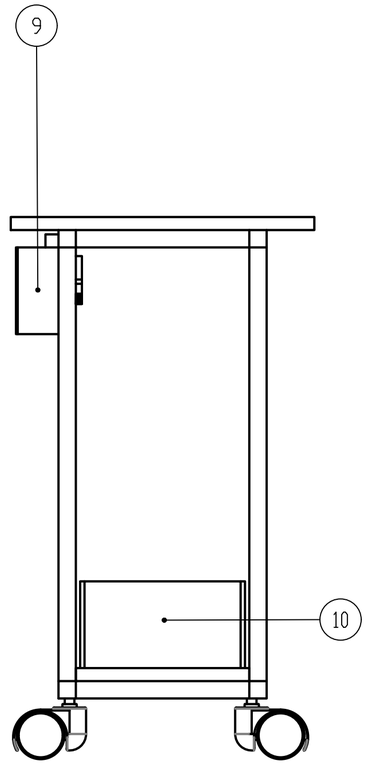
ESCALA N/A

N/A

Appendix C

Mechanical Diagrams





SPECIFICATIONS	
TYPE	NON-INVASIVE
V.C.C.	5 VDC
AMPLF. SRC.	±4.5 VDC
GND.	0 VDC
APPRX. WGHT.	10 kg
CHANNELS	10
SMPL. RATE	250 Hz
SENSOR	ELECTRODE
DATA STORAGE	EDF FORMAT
GAIN	50.4
FREQ. RANGE	1 Hz -45 Hz
ADC RESLTN.	10 BITS
COMM. SPEED	115200 BAUDS

POS	ZONE	DENOMINATION	QTY	MATERIAL	DRAWING	OBSERVATIONS
10	7D	AUXILIARY LATERAL BOX	1	MDF WOOD	N/A	100x180x10 mm
9	6B	CIRCUIT BOX LID	1	PLA	D03-007	
8	2C	CABLES HOOK	1	PLA	N/A	
7	2C	BATTERY LID	1	PLA	D03-006	
6	3E	LOWER TABLE	1	MDF WOOD	D03-005	
5	4D	CHAIR WHEELS	1	VARIOUS	N/A	
4	4D	AUXILIARY FRONTAL BOX	1	MDF WOOD	N/A	100x400x10 mm
3	4C	STEEL STRUCTURE	1	STEEL	D03-004	
2	3B	CIRCUIT CASE	1	PLA	D03-003	
1	2B	UPPER TABLE	1	MDF WOOD	D03-002	

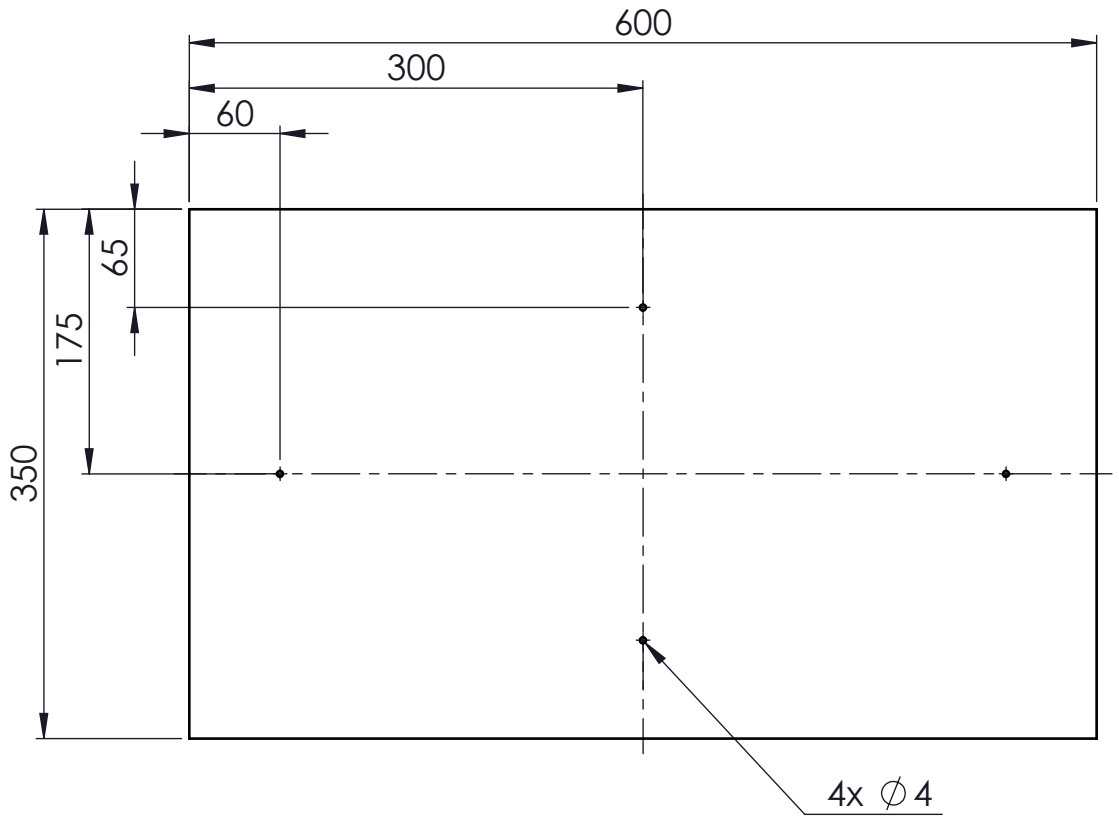
UIDE MECHATRONICS ENGINEERING

DWN.	TOBAR M.	13/10/22
DES.	TOBAR M.	10/10/22
REV.	TIRIRA A.	15/10/22

EEG SYSTEM THAT CAPTURES BRAIN WAVES, DISPLAYS THEM AND DETECTS EPILEPSY

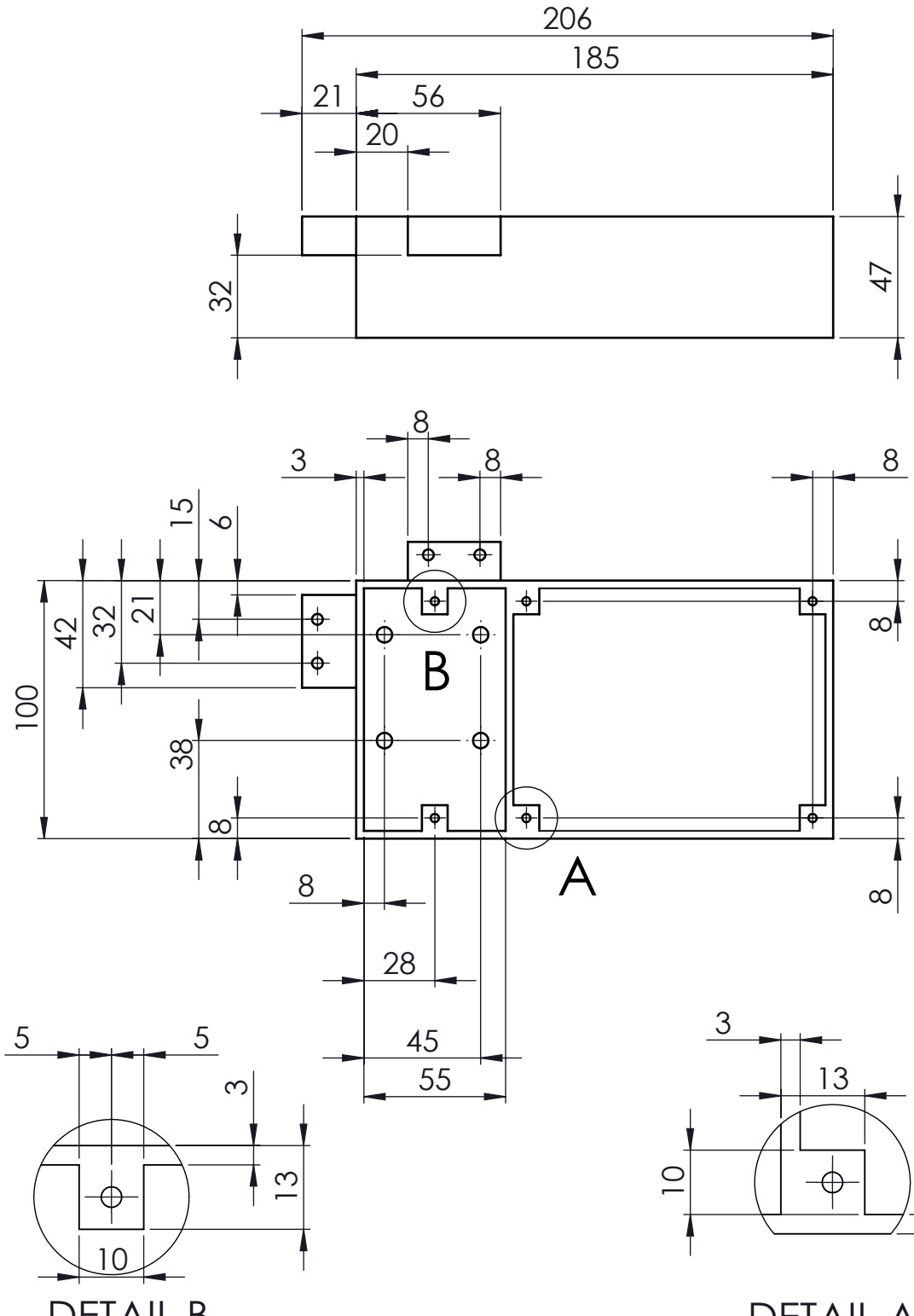
D03 - 001

SCALE: 1:5



Notes:
- Thickness is 25 mm
- All perforations are full perforations.

TREATMENT:	NO TREATMENT		**UIDE**	MECHATRONICS ENGINEERING		
COATING:	NO COATING					
MATERIAL: MELAMINIC MDF		TOL. GRAL: +-1	SCALE: 1:5	DW:	TOBAR M.	13/10/22
				DES:	TOBAR M.	10/10/22
				REV:	TIRIRA A.	15/10/22
UPPER TABLE			D03 - 002			

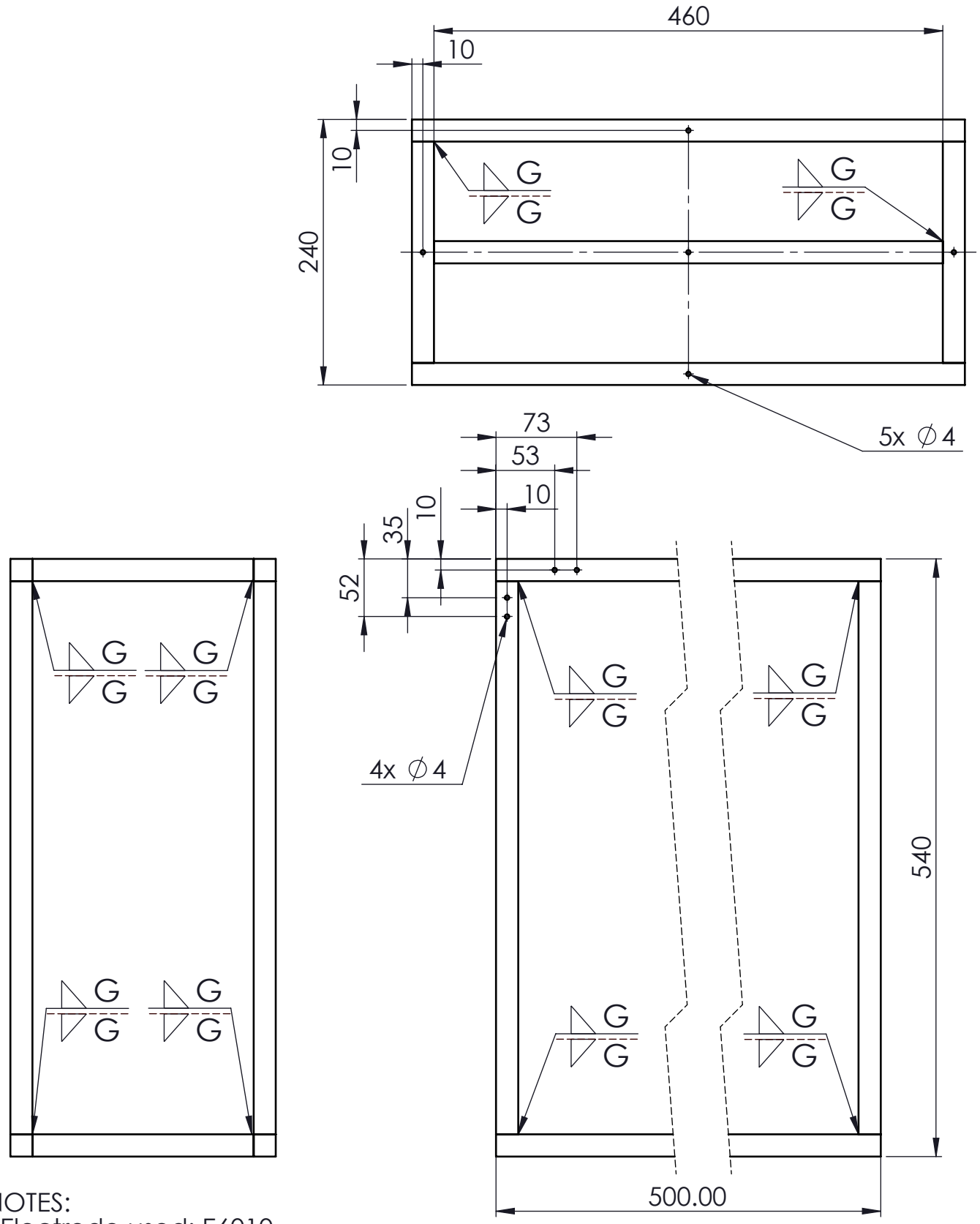


DETAIL B
SCALE 1 : 1

DETAIL A
SCALE 1 : 1

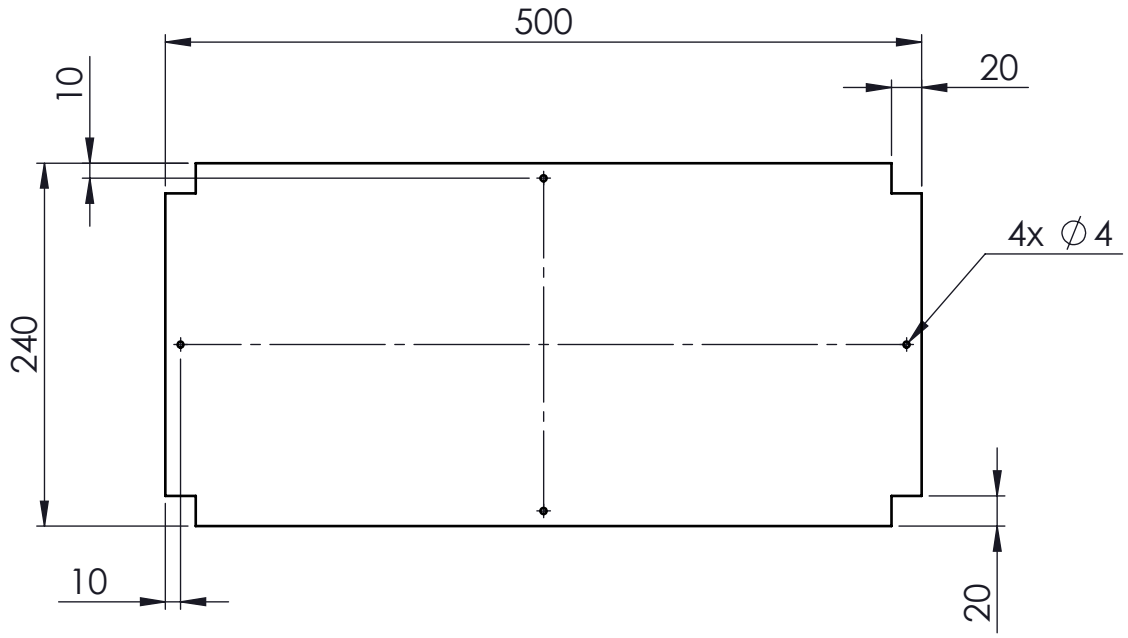
Note:
All perforations are full perforations

TREATMENT:	NO TREATMENT	**UIDE**	MECHATRONICS ENGINEERING			
COATING:	NO COATING					
MATERIAL: PLA	TOL. GRAL: +-1	SCALE: 1: 2,5	DW:	TOBAR M.	13/10/22	
			DES:	TOBAR M.	10/10/22	
			REV:	TIRIRA A.	15/10/22	
CIRCUIT CASE		D03 - 003				



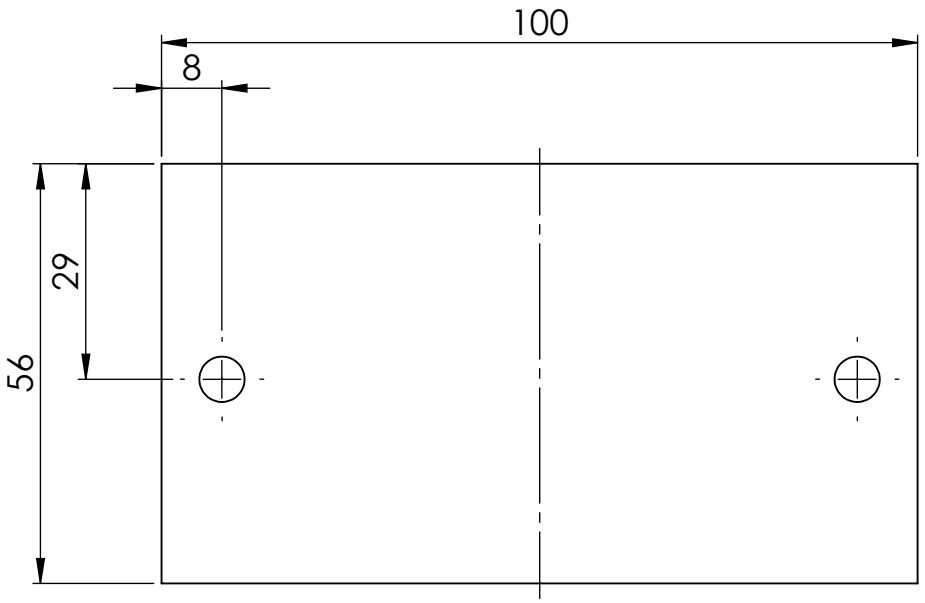
NOTES:
- Electrode used: E6010
- Structure made of 20x20 mm steel square pipes with wall 1.2 mm thickness.
- G: Grinded after weld.

TREATMENT:	NO TREATMENT	**UIDE**	MECHATRONICS ENGINEERING			
COATING:	NO COATING					
MATERIAL: STEEL	TOL. GRAL: +-1	SCALE: 1: 5	DW:	TOBAR M.	13/10/22	
			DES:	TOBAR M.	10/10/22	
			REV:	TIRIRA A.	15/10/22	
STEEL STRUCTURE		D03 - 004				



Notes:
- Thickness: 25 mm
- All perforations are full perforations

TREATMENT:	NO TREATMENT	**UIDE**	MECHATRONICS ENGINEERING			
COATING:	NO COATING					
MATERIAL: MELAMINIC MDF	TOL. GRAL: +-1	SCALE: 1:5	DW:	TOBAR M.	13/10/22	
			DES:	TOBAR M.	10/10/22	
			REV:	TIRIRA A.	15/10/22	
LOWER TABLE		D03 - 005				



NOTES:

-Thickness: 2 mm
-All perforations are full perforations.

TREATMENT:	NO TREATMENT	**UIDE**	MECHATRONICS ENGINEERING			
COATING:	NO COATING					
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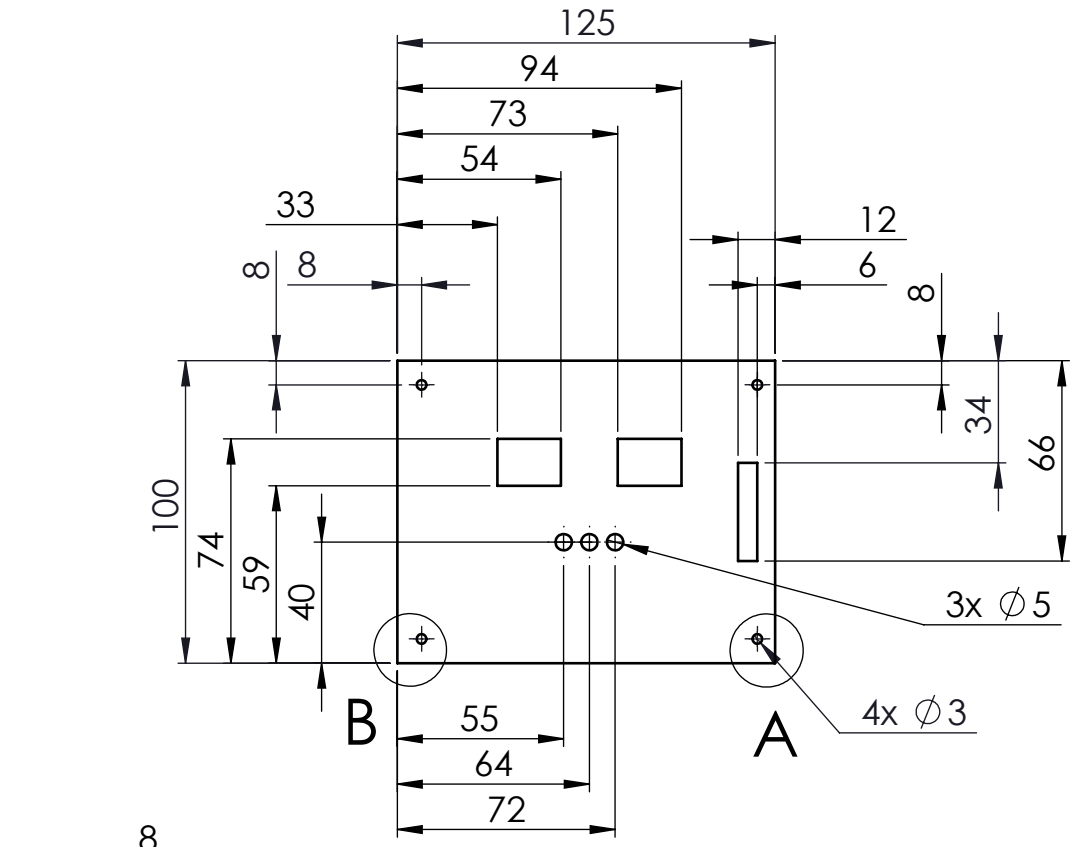
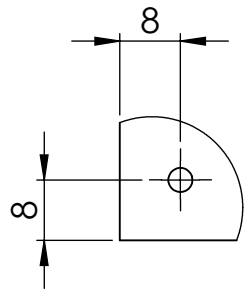
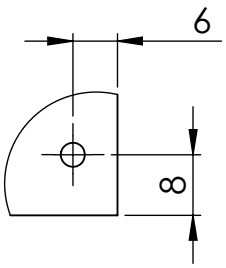
BATTERY LID		D03 - 006				





DETAIL B
SCALE 1 : 1



DETAIL A
SCALE 1 : 1

NOTES:

-Thickness: 2 mm
-All perforations are full perforations.

TREATMENT:	NO TREATMENT		**UIDE**	MECHATRONICS ENGINEERING			
COATING:	NO COATING						
MATERIAL: PLA		TOL. GRAL: +-1	SCALE: 1: 2,5	DW:	TOBAR M.	13/10/22	
				DES:	TOBAR M.	10/10/22	
				REV:	TIRIRA A.	15/10/22	
CIRCUIT CASE LID			D03 - 007				

Appendix D

User Manual

Electroencephalograph Prototype for the Acquisition and Visualization of Brain Signals, Which by Means of Neural Networks Allows the Detection of Epilepsy User Manual

Martín Tobar

January 28, 2023

Contents

1 Introduction

Welcome to the user manual for the electroencephalograph (EEG) prototype I have developed. The EEG is a non-invasive medical device that measures the electrical activity of the brain using sensors called electrodes attached to the scalp. The recorded signal is processed and analyzed by a medical specialist, usually a neurologist, to detect any abnormalities or disorders in the brain. This prototype is designed to perform the acquisition, processing, and visualization of brain signals, and to use a neural network algorithm to detect epilepsy based on the patterns obtained. This manual will provide an overview of the features and functions of the EEG prototype, as well as step-by-step instructions on how to use it. I hope that this manual will help you to get the most out of this innovative and useful tool.

2 Safety considerations:

- Do not place the EEG prototype near sources of heat or moisture, or expose it to direct sunlight.
- Do not attempt to disassemble or modify the EEG prototype.
- Do not touch any exposed electrical components of the EEG prototype.

- Follow all instructions and warnings provided in the manual when using the EEG prototype.
- If the EEG prototype is not functioning properly, stop the use immediately and contact the manufacturer for assistance.
- Wear protective equipment, such as gloves and goggles, when handling the EEG prototype or its components.
- Keep the EEG prototype out of the reach of children and pets.
- Do not use the EEG prototype if you are pregnant or have any medical conditions that may be affected by exposure to electrical signals.
- If you experience any discomfort or adverse effects while using the EEG prototype, stop the use immediately and consult a medical professional.
- The EEG prototype must be handled and used only by personal that is capable, such as technicians or neurologists.

3 Technical specifications

The important specifications of the project can be seen in Table 1.

Table 1: General specifications of the prototype

TYPE	NON-INVASIVE
VCC	5 VDC
AMPLIFIER SOURCE	$\pm$4.5 VDC
GND	0 VDC
HEIGHT	625 mm
WIDTH	600 mm
DEPTH	350 mm
APPROXIMATE WEIGHT	10 kg
AMOUNT OF CHANNELS	10
SAMPLING RATE	250 Hz
SENSOR	ELECTRODE
DATA STORAGE	EDF FORMAT
GAIN	50.4
BRAIN WAVE FREQUENCY RANGE	1 Hz to 45 Hz
ADC RESOLUTION	10 bits
COMMUNICATION SPEED	115 200 BAUDS

4 Requirements

- A computer with a USB port.
- A compatible operating system, such as Windows 10, Windows 11, macOS, or Linux.
- Enough storage space to save recorded EEG data and software files. It is estimated that it is needed 1 MB per 3 minutes recording. Therefore, 1 GB will be enough for 51.2 hours of recording.
- A PDF viewer (optional, for viewing exported PDF files).
- 9VDC batteries to replace when the one in use is discharged.

5 Using the EEG prototype

To use the EEG, first check that there is a battery placed and that it is charged. Without the battery the amplifiers will not work and the waves will not be captured. After this, connect the USB cable to a computer. Once it is connected there are two buttons on the EEG. The one on the left will turn on the amplifiers while the one on the right will turn on the remaining elements. There are two buttons because the amplifiers are fed with 9VDC so they can receive $\pm$ 4.5DC while the rest of the circuit receives 5 VDC. If the green LED turns on, it means that the amplifiers are on. If the orange LED turns on, it means that the 5V are going through the remaining circuit. To know if everything is working correctly, one must wait for the blue LED to turn on and then blink. Once it has blinked and stays on, it means that the whole system is ready to work.

The software developed is easy to use and is user-friendly. The application is composed of a main screen which can be seen in Fig. 1 which allows the user to choose between making a new recording, show a past recording or to make the epileptic analysis on a recording. If the user chooses the ”MAKE EEG” option, the

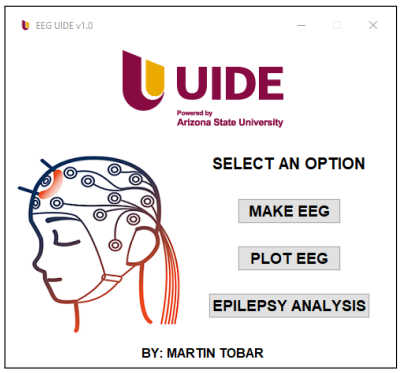


Figure 1: Main screen that appears when the software is opened up.

Maker screen will appear and can be seen in Fig. 2 and that allows the user to enter the patient’s name, the doctor’s name and to select the duration in seconds in intervals of 30 seconds. Once all the data is entered, the user must press start and the system will activate, the text will change to let the user the EEG is in progress and a counter will begin as can be seen in Fig. 3. Also there is a pop-up notification to tell the user the recording is finished.

If the user selects the ”PLOT EEG” option, a file dialog will pop-up and let the user choose between EDF files. Once a file is chosen, a window will pop-up and allow the user to choose between plotting the whole recording along with its frequency spectrum, or just an specific brain frequency as alpha, beta, etc. Also there is the option to export the EDF file in PDF format. All these features can be seen in Fig. 4. Finally, if the user selects the ”Epilepsy Detection” option, a file dialog will pop-up and let the user choose an EDF file

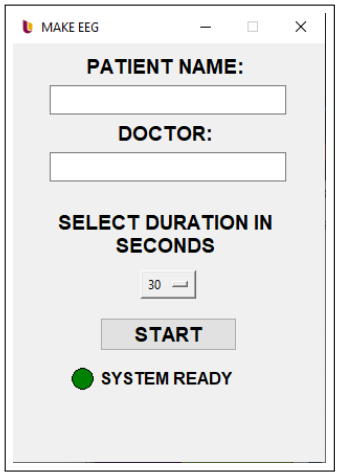


Figure 2: EEG recorder screen when opened up.

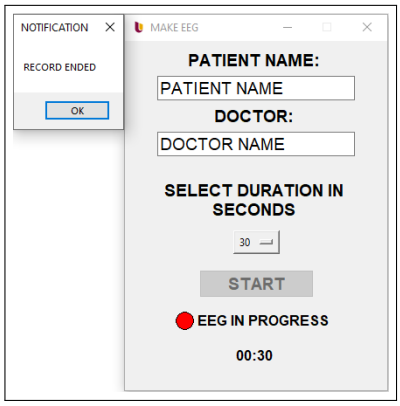


Figure 3: Make screen that appears when the EEG recording is finished.

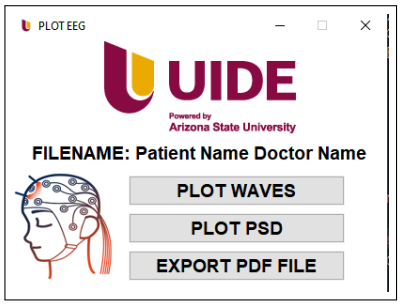


Figure 4: Screen that allows the user tho choose between different plotting options.

in which the CNN binary classification algorithm will run. Once the EDF file is chosen and the classification is finished, a notification will pop-up and let the user know if this file contains epilepsy patterns or not. These notification can be seen in Fig. 5 Also, there are some options that are available in the interactive plotting. This options can be seen in Fig. 6.

It is important to highlight that electrodes 1, 2 and 3 are used for the neural network. Therefore, they must be ”FP2”, ”C4” and ”Cz” respectively. Only these channels are used as input for the neural network, therefore

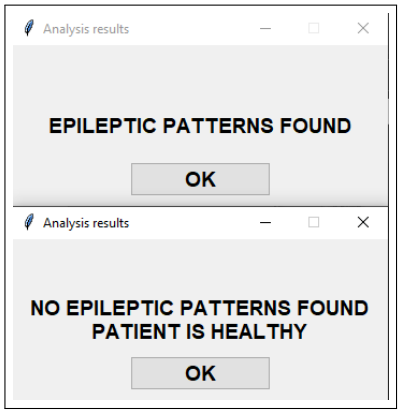


Figure 5: Notifications shown depending if epilepsy was detected or not.

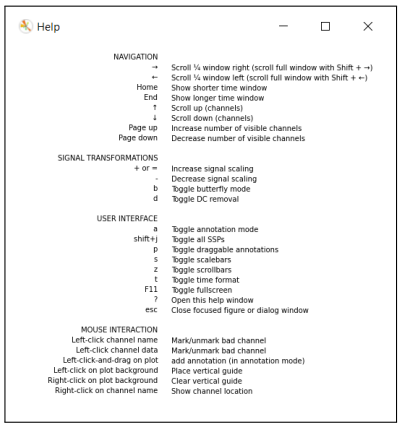


Figure 6: Options available in the software interactive plotter.

the information in the other 7 channels is not important in this aspect, but could be important depending on the user needs. There are many montage standards, but the one suggested is the 10-20 standard.

6 Troubleshooting

As the software program has not being tested openly by public there has not been a huge feedback nor bugs report, therefore there might exist some bugs that might make the program fail but this can be fixed with time when people report the bugs and the author creates a patch/update. So far, it is recommended that if there is any error, first turn off both switches and then disconnect the USB cable from the computer. Once this is done, connect the USB cable back and turn both switches on, this fix will reset the whole system completely which will likely fix any bugs.

7 Maintenance

The only maintenance needed is to change the battery periodically when it is discharged. It is advised that once it is seen that the typical measurements of the EEG is around the range of 0.06 V, check the battery voltage as this means that the battery is discharged. To change the battery, simply remove the small lid from the case with a screwdriver, replace the battery and then put the lid back.

Appendix E

Datasheets

Low Cost Low Power Instrumentation Amplifier

AD620

FEATURES

Easy to use
- **Gain set with one external resistor (Gain range 1 to 10,000)**
- **Wide power supply range (±2.3 V to ±18 V)**
- **Higher performance than 3 op amp IA designs**
- **Available in 8-lead DIP and SOIC packaging**
- **Low power, 1.3 mA max supply current**

Excellent dc performance (B grade)
- **50 µV max, input offset voltage**
- **0.6 µV/°C max, input offset drift**
- **1.0 nA max, input bias current**
- **100 dB min common-mode rejection ratio (G = 10)**

Low noise
- **9 nV/√Hz @ 1 kHz, input voltage noise**
- **0.28 µV p-p noise (0.1 Hz to 10 Hz)**

Excellent ac specifications
- **120 kHz bandwidth (G = 100)**
- **15 µs settling time to 0.01%**

APPLICATIONS

Weigh scales
ECG and medical instrumentation
Transducer interface
Data acquisition systems
Industrial process controls
Battery-powered and portable equipment

Table 1. Next Generation Upgrades for AD620

Part	Comment
AD8221	Better specs at lower price
AD8222	Dual channel or differential out
AD8226	Low power, wide input range
AD8220	JFET input
AD8228	Best gain accuracy
AD8295	+2 precision op amps or differential out
AD8429	Ultra low noise

CONNECTION DIAGRAM

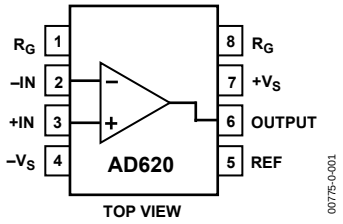


Figure 1. 8-Lead PDIP (N), CERDIP (Q), and SOIC (R) Packages

PRODUCT DESCRIPTION

The AD620 is a low cost, high accuracy instrumentation amplifier that requires only one external resistor to set gains of 1 to 10,000. Furthermore, the AD620 features 8-lead SOIC and DIP packaging that is smaller than discrete designs and offers lower power (only 1.3 mA max supply current), making it a good fit for battery-powered, portable (or remote) applications.

The AD620, with its high accuracy of 40 ppm maximum nonlinearity, low offset voltage of 50 µV max, and offset drift of 0.6 µV/°C max, is ideal for use in precision data acquisition systems, such as weigh scales and transducer interfaces. Furthermore, the low noise, low input bias current, and low power of the AD620 make it well suited for medical applications, such as ECG and noninvasive blood pressure monitors.

The low input bias current of 1.0 nA max is made possible with the use of Superβeta processing in the input stage. The AD620 works well as a preamplifier due to its low input voltage noise of 9 nV/√Hz at 1 kHz, 0.28 µV p-p in the 0.1 Hz to 10 Hz band, and 0.1 pA/√Hz input current noise. Also, the AD620 is well suited for multiplexed applications with its settling time of 15 µs to 0.01%, and its cost is low enough to enable designs with one in-amp per channel.

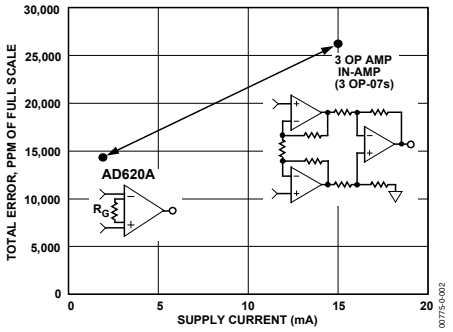


Figure 2. Three Op Amp IA Designs vs. AD620

Rev. H

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Added Figure 41; Renumbered Sequentially 15
Changes to AD620ACHIPS Information Section 18
Updated Ordering Guide 20

12/04—Rev. F to Rev. G

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SPECIFICATIONS

Typical @ 25°C, V_S = ±15 V, and R_L = 2 kΩ, unless otherwise noted.

Table 2.

		AD620A			AD620B			AD620S[1]			
Parameter	**Conditions**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Unit**
GAIN	G = 1 + (49.4 kΩ/R_G)										
Gain Range		1		10,000	1		10,000	1		10,000	
Gain Error[2]	V_{OUT} = ±10 V										
G = 1			0.03	0.10		0.01	0.02		0.03	0.10	%
G = 10			0.15	0.30		0.10	0.15		0.15	0.30	%
G = 100			0.15	0.30		0.10	0.15		0.15	0.30	%
G = 1000			0.40	0.70		0.35	0.50		0.40	0.70	%
Nonlinearity	V_{OUT} = −10 V to +10 V										
G = 1–1000	R_L = 10 kΩ		10	40		10	40		10	40	ppm
G = 1–100	R_L = 2 kΩ		10	95		10	95		10	95	ppm
Gain vs. Temperature											
	G = 1			10			10			10	ppm/°C
	Gain >1[2]			−50			−50			−50	ppm/°C
VOLTAGE OFFSET	(Total RTI Error = V_{OSI} + V_{OSO}/G)										
Input Offset, V_{OSI}	V_S = ±5 V to ± 15 V		30	125		15	50		30	125	µV
Overtemperature	V_S = ±5 V to ± 15 V			185			85			225	µV
Average TC	V_S = ±5 V to ± 15 V		0.3	1.0		0.1	0.6		0.3	1.0	µV/°C
Output Offset, V_{OSO}	V_S = ±15 V		400	1000		200	500		400	1000	µV
	V_S = ± 5 V			1500			750			1500	µV
Overtemperature	V_S = ±5 V to ± 15 V			2000			1000			2000	µV
Average TC	V_S = ±5 V to ± 15 V		5.0	15		2.5	7.0		5.0	15	µV/°C
Offset Referred to the Input vs. Supply (PSR)	V_S = ±2.3 V to ±18 V										
G = 1		80	100		80	100		80	100		dB
G = 10		95	120		100	120		95	120		dB
G = 100		110	140		120	140		110	140		dB
G = 1000		110	140		120	140		110	140		dB
INPUT CURRENT											
Input Bias Current			0.5	2.0		0.5	1.0		0.5	2	nA
Overtemperature				2.5			1.5			4	nA
Average TC			3.0			3.0			8.0		pA/°C
Input Offset Current			0.3	1.0		0.3	0.5		0.3	1.0	nA
Overtemperature				1.5			0.75			2.0	nA
Average TC			1.5			1.5			8.0		pA/°C
INPUT											
Input Impedance											
Differential			10||2			10||2			10||2		GΩ_pF
Common-Mode			10||2			10||2			10||2		GΩ_pF
Input Voltage Range[3]	V_S = ±2.3 V to ±5 V	$-V_S$ + 1.9		$+V_S$ − 1.2	$-V_S$ + 1.9		$+V_S$ − 1.2	$-V_S$ + 1.9		$+V_S$ − 1.2	V
Overtemperature		$-V_S$ + 2.1		$+V_S$ − 1.3	$-V_S$ + 2.1		$+V_S$ − 1.3	$-V_S$ + 2.1		$+V_S$ − 1.3	V
	V_S = ± 5 V to ±18 V	$-V_S$ + 1.9		$+V_S$ − 1.4	$-V_S$ + 1.9		$+V_S$ − 1.4	$-V_S$ + 1.9		$+V_S$ − 1.4	V
Overtemperature		$-V_S$ + 2.1		$+V_S$ − 1.4	$-V_S$ + 2.1		$+V_S$ + 2.1	$-V_S$ + 2.3		$+V_S$ − 1.4	V

Parameter	Conditions	AD620A Min	AD620A Typ	AD620A Max	AD620B Min	AD620B Typ	AD620B Max	AD620S[1] Min	AD620S[1] Typ	AD620S[1] Max	Unit
Common-Mode Rejection											
Ratio DC to 60 Hz with											
1 kΩ Source Imbalance	V_{CM} = 0 V to ± 10 V										
G = 1		73	90		80	90		73	90		dB
G = 10		93	110		100	110		93	110		dB
G = 100		110	130		120	130		110	130		dB
G = 1000		110	130		120	130		110	130		dB
OUTPUT											
Output Swing	R_L = 10 kΩ										
	V_S = ±2.3 V to ± 5 V	$-V_S$ + 1.1		$+V_S$ – 1.2	$-V_S$ + 1.1		$+V_S$ – 1.2	$-V_S$ + 1.1		$+V_S$ – 1.2	V
Overtemperature		$-V_S$ + 1.4		$+V_S$ – 1.3	$-V_S$ + 1.4		$+V_S$ – 1.3	$-V_S$ + 1.6		$+V_S$ – 1.3	V
	V_S = ±5 V to ± 18 V	$-V_S$ + 1.2		$+V_S$ – 1.4	$-V_S$ + 1.2		$+V_S$ – 1.4	$-V_S$ + 1.2		$+V_S$ – 1.4	V
Overtemperature		$-V_S$ + 1.6		$+V_S$ – 1.5	$-V_S$ + 1.6		$+V_S$ – 1.5	$-V_S$ + 2.3		$+V_S$ – 1.5	V
Short Circuit Current			±18			±18			±18		mA
DYNAMIC RESPONSE											
Small Signal –3 dB Bandwidth											
G = 1			1000			1000			1000		kHz
G = 10			800			800			800		kHz
G = 100			120			120			120		kHz
G = 1000			12			12			12		kHz
Slew Rate		0.75	1.2		0.75	1.2		0.75	1.2		V/µs
Settling Time to 0.01%	10 V Step										
G = 1–100			15			15			15		µs
G = 1000			150			150			150		µs
NOISE											
Voltage Noise, 1 kHz	$Total\ RTI\ Noise = \sqrt{(e^2_{ni})} + (e_{no}/G)^2$										
Input, Voltage Noise, e_{ni}			9	13		9	13		9	13	nV/√Hz
Output, Voltage Noise, e_{no}			72	100		72	100		72	100	nV/√Hz
RTI, 0.1 Hz to 10 Hz											
G = 1			3.0			3.0	6.0		3.0	6.0	µV p-p
G = 10			0.55			0.55	0.8		0.55	0.8	µV p-p
G = 100–1000			0.28			0.28	0.4		0.28	0.4	µV p-p
Current Noise	f = 1 kHz		100			100			100		fA/√Hz
0.1 Hz to 10 Hz			10			10			10		pA p-p
REFERENCE INPUT											
R_{IN}			20			20			20		kΩ
I_{IN}	V_{IN+}, V_{REF} = 0		50	60		50	60		50	60	µA
Voltage Range		$-V_S$ + 1.6		$+V_S$ – 1.6	$-V_S$ + 1.6		$+V_S$ – 1.6	$-V_S$ + 1.6		$+V_S$ – 1.6	V
Gain to Output		1 ± 0.0001			1 ± 0.0001			1 ± 0.0001			
POWER SUPPLY											
Operating Range[4]		±2.3		±18	±2.3		±18	±2.3		±18	V
Quiescent Current	V_S = ±2.3 V to ±18 V		0.9	1.3		0.9	1.3		0.9	1.3	mA
Overtemperature			1.1	1.6		1.1	1.6		1.1	1.6	mA
TEMPERATURE RANGE											
For Specified Performance		–40 to +85			–40 to +85			–55 to +125			°C

[1] See Analog Devices military data sheet for 883B tested specifications.
[2] Does not include effects of external resistor R_G.
[3] One input grounded. G = 1.
[4] This is defined as the same supply range that is used to specify PSR.

ABSOLUTE MAXIMUM RATINGS

Table 3.

Parameter	Rating
Supply Voltage	±18 V
Internal Power Dissipation[1]	650 mW
Input Voltage (Common-Mode)	$\pm V_S$
Differential Input Voltage	25 V
Output Short-Circuit Duration	Indefinite
Storage Temperature Range (Q)	−65°C to +150°C
Storage Temperature Range (N, R)	−65°C to +125°C
Operating Temperature Range	
AD620 (A, B)	−40°C to +85°C
AD620 (S)	−55°C to +125°C
Lead Temperature Range	
(Soldering 10 seconds)	300°C

[1] Specification is for device in free air:
8-Lead Plastic Package: θ_{JA} = 95°C
8-Lead CERDIP Package: θ_{JA} = 110°C
8-Lead SOIC Package: θ_{JA} = 155°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other condition s above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

TYPICAL PERFORMANCE CHARACTERISTICS

(@ 25°C, V_S = ±15 V, R_L = 2 kΩ, unless otherwise noted.)

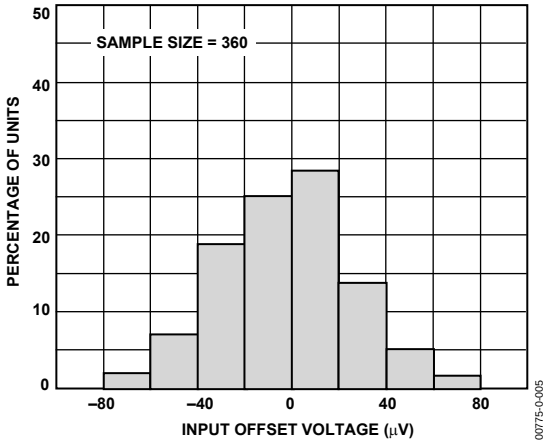

Figure 3. Typical Distribution of Input Offset Voltage

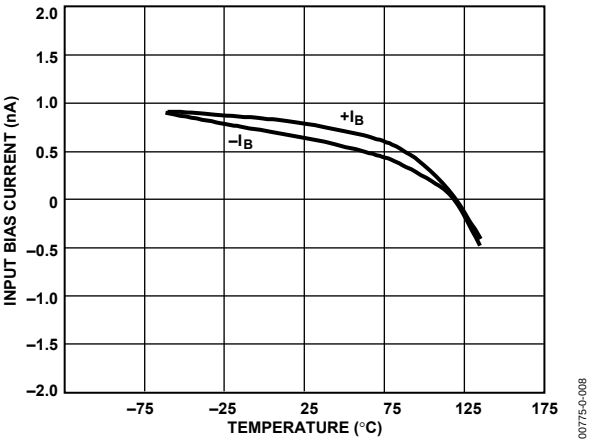

Figure 6. Input Bias Current vs. Temperature

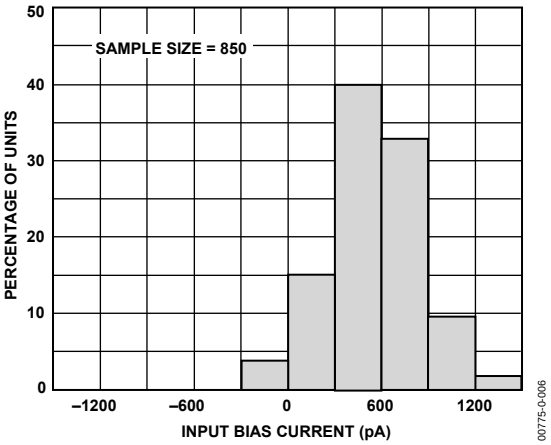

Figure 4. Typical Distribution of Input Bias Current

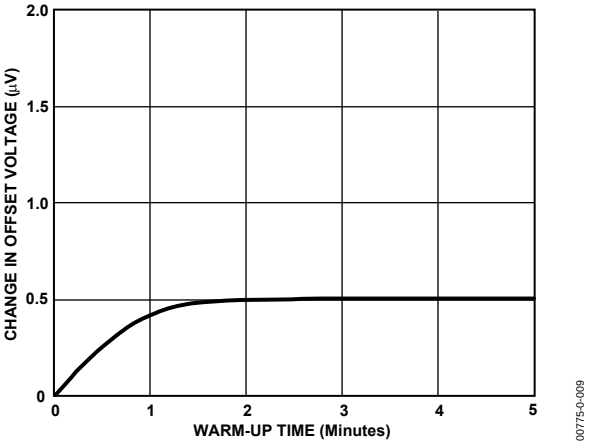

Figure 7. Change in Input Offset Voltage vs. Warm-Up Time

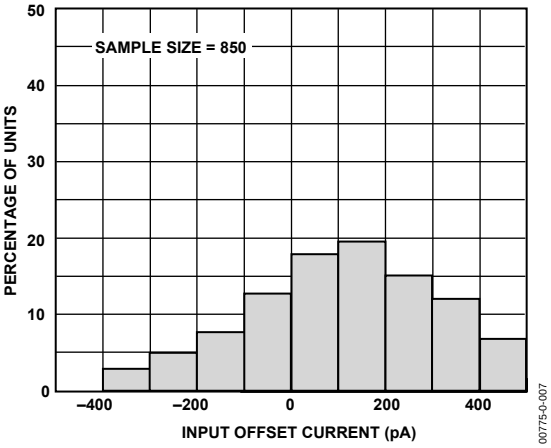

Figure 5. Typical Distribution of Input Offset Current

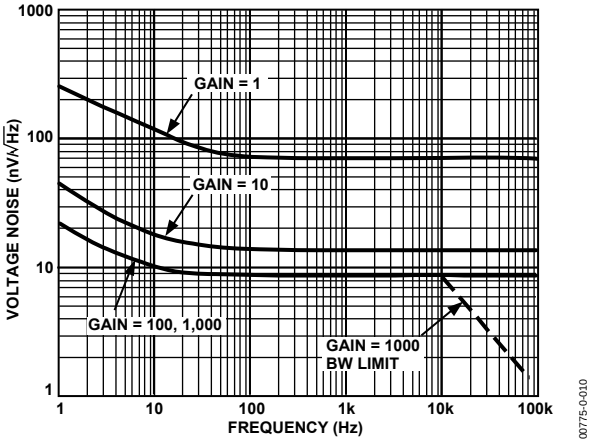

Figure 8. Voltage Noise Spectral Density vs. Frequency (G = 1–1000)

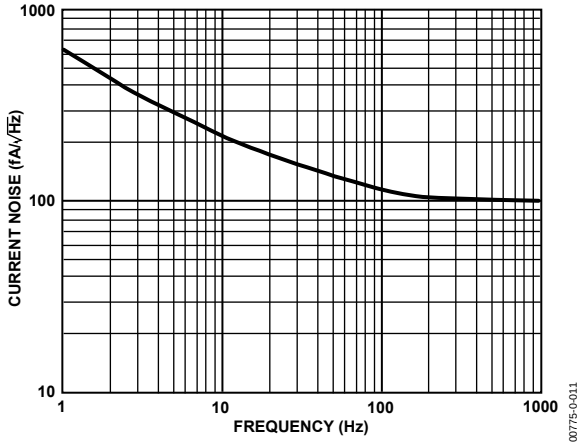

Figure 9. Current Noise Spectral Density vs. Frequency

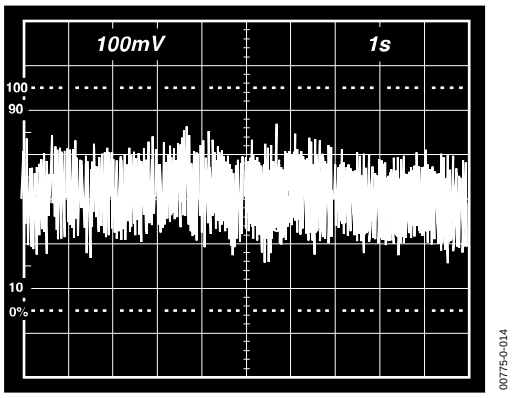

Figure 12. 0.1 Hz to 10 Hz Current Noise, 5 pA/Div

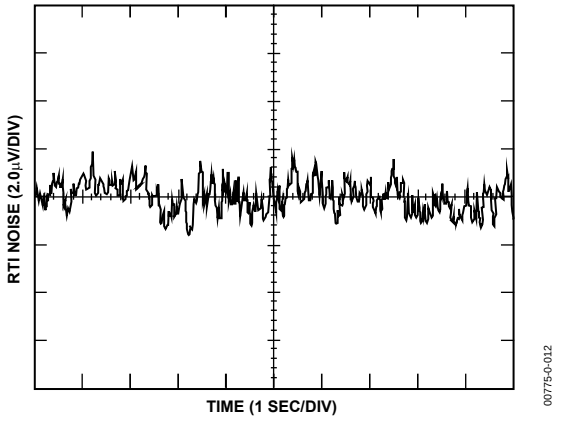

Figure 10. 0.1 Hz to 10 Hz RTI Voltage Noise (G = 1)

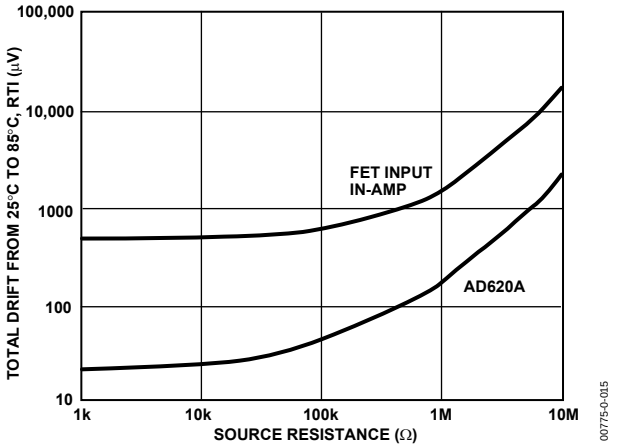

Figure 13. Total Drift vs. Source Resistance

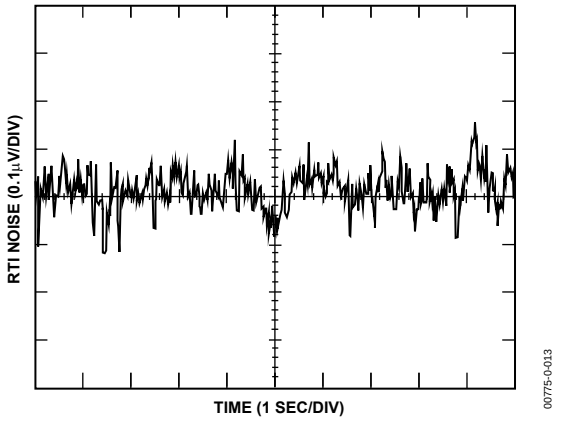

Figure 11. 0.1 Hz to 10 Hz RTI Voltage Noise (G = 1000)

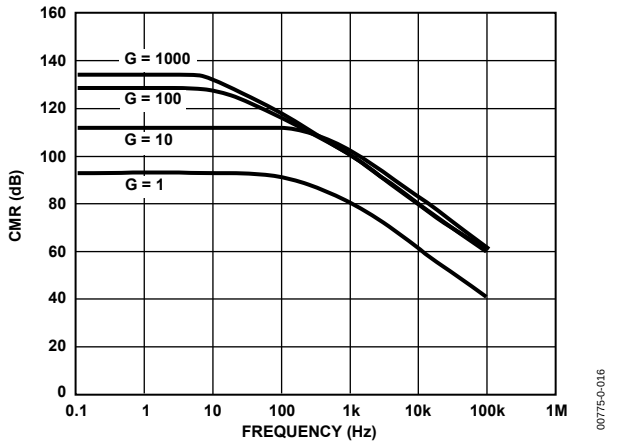

Figure 14. Typical CMR vs. Frequency, RTI, Zero to 1 kΩ Source Imbalance

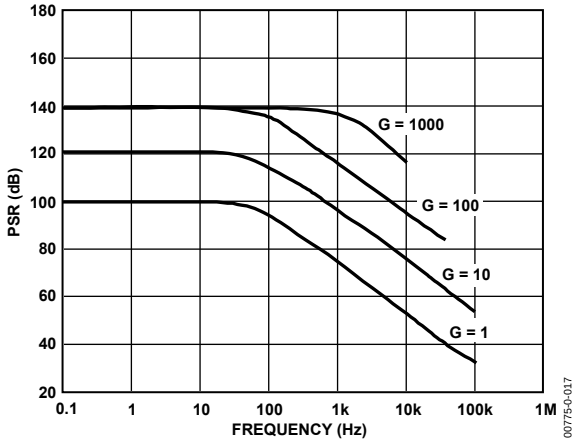

Figure 15. Positive PSR vs. Frequency, RTI (G = 1–1000)

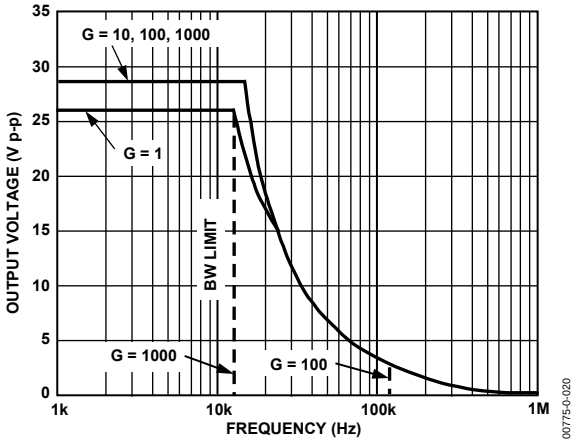

Figure 18. Large Signal Frequency Response

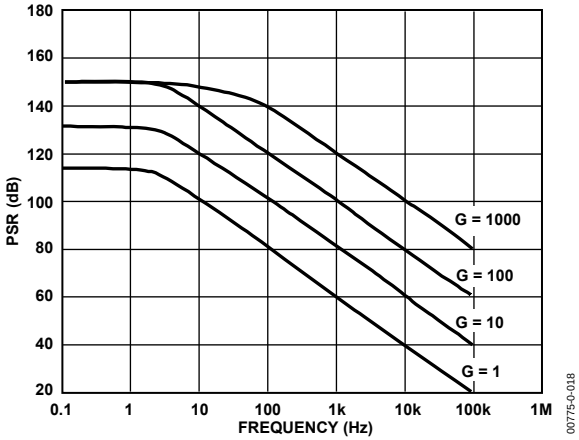

Figure 16. Negative PSR vs. Frequency, RTI (G = 1–1000)

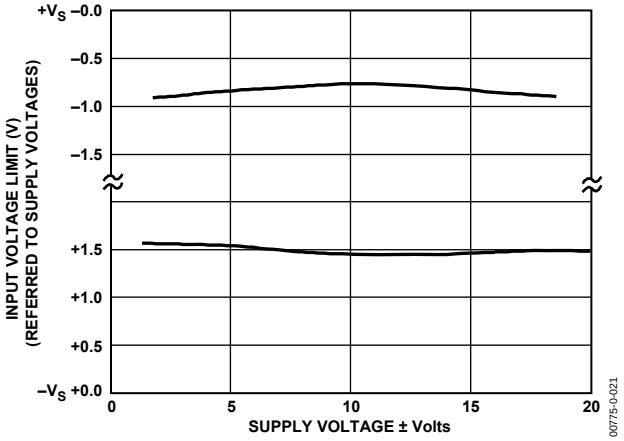

Figure 19. Input Voltage Range vs. Supply Voltage, G = 1

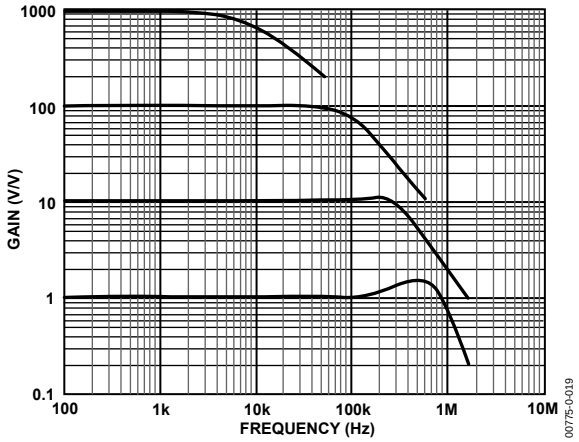

Figure 17. Gain vs. Frequency

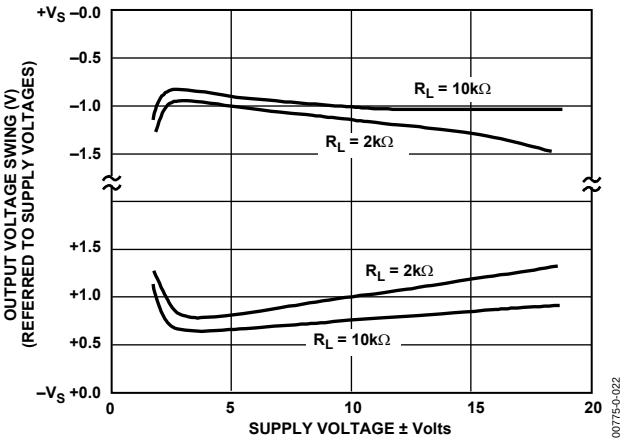

Figure 20. Output Voltage Swing vs. Supply Voltage, G = 10

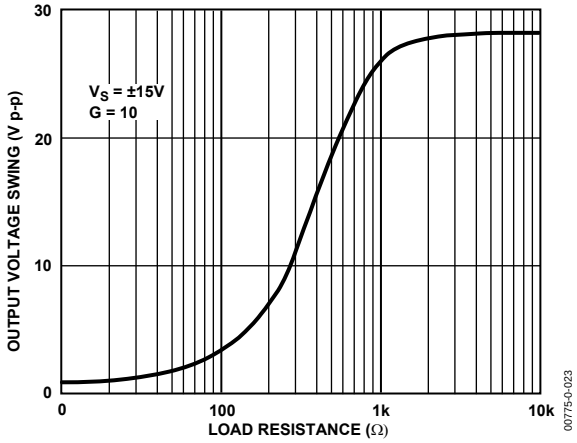

Figure 21. Output Voltage Swing vs. Load Resistance

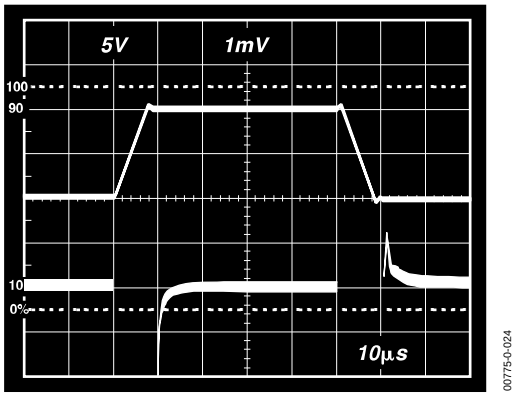

Figure 22. Large Signal Pulse Response and Settling Time
G = 1 (0.5 mV = 0.01%)

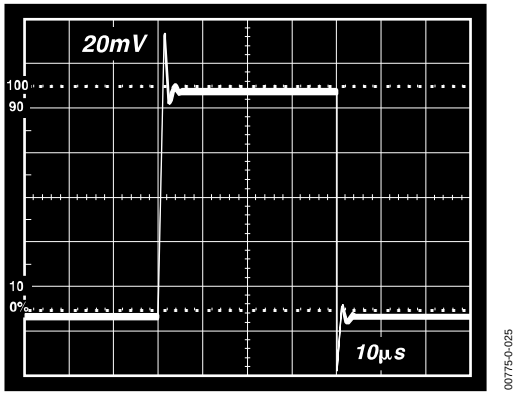

Figure 23. Small Signal Response, G = 1, R_L = 2 kΩ, C_L = 100 pF

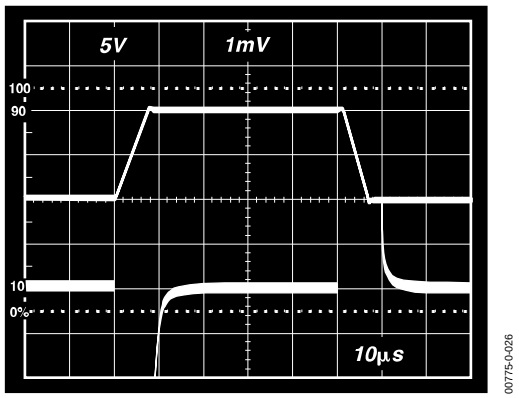

Figure 24. Large Signal Response and Settling Time, G = 10 (0.5 mV = 0.01%)

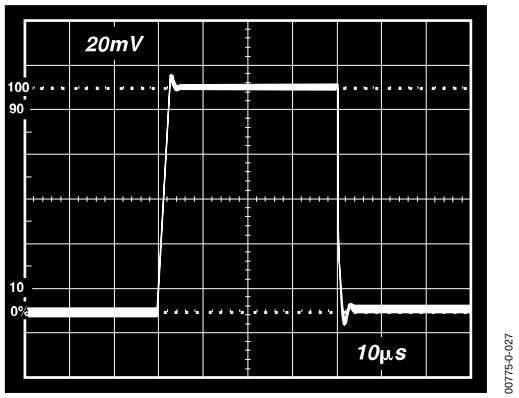

Figure 25. Small Signal Response, G = 10, R_L = 2 kΩ, C_L = 100 pF

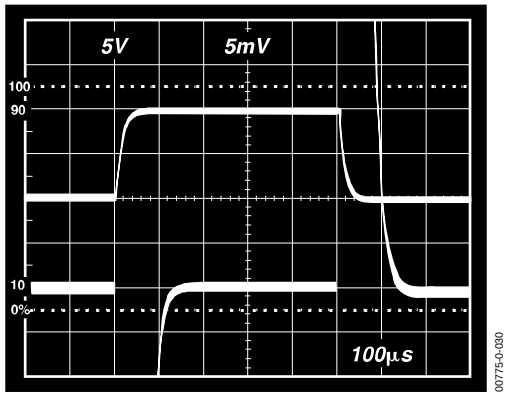

Figure 26. Large Signal Response and Settling Time, G = 100 (0.5 mV = 0.01%)

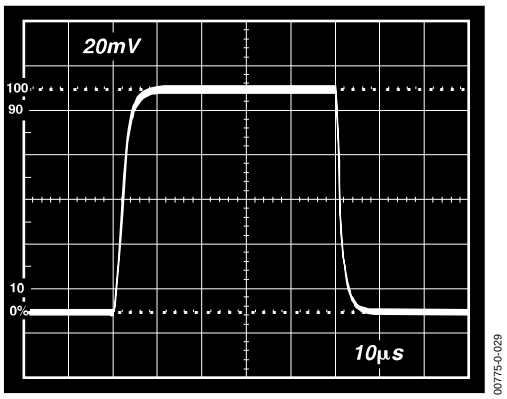

Figure 27. Small Signal Pulse Response, G = 100, R_L = 2 kΩ, C_L = 100 pF

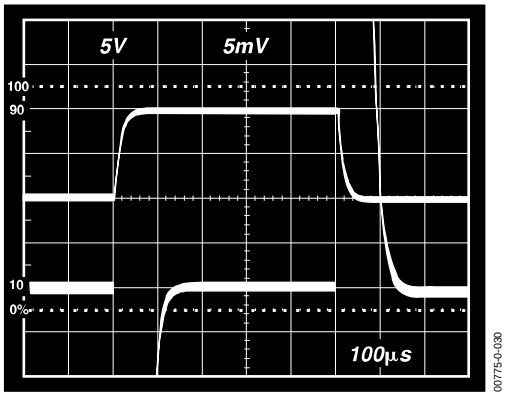

Figure 28. Large Signal Response and Settling Time, G = 1000 (0.5 mV = 0.01%)

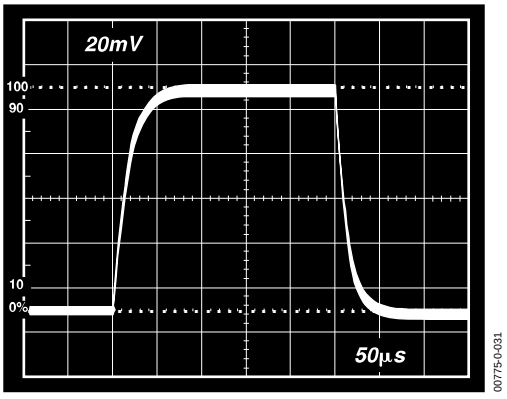

Figure 29. Small Signal Pulse Response, G = 1000, R_L = 2 kΩ, C_L = 100 pF

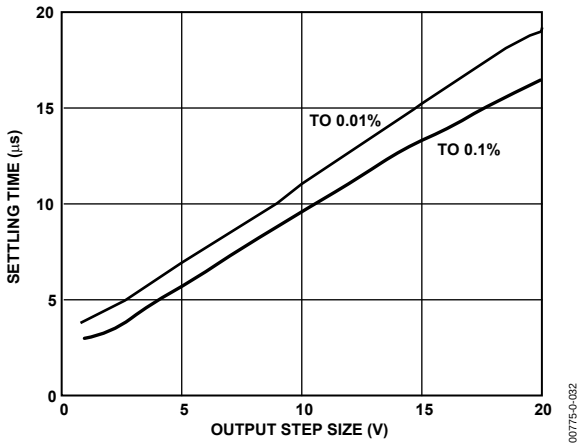

Figure 30. Settling Time vs. Step Size (G = 1)

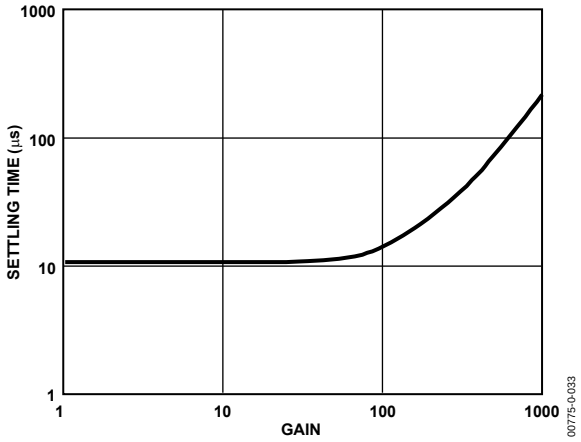

Figure 31. Settling Time to 0.01% vs. Gain, for a 10 V Step

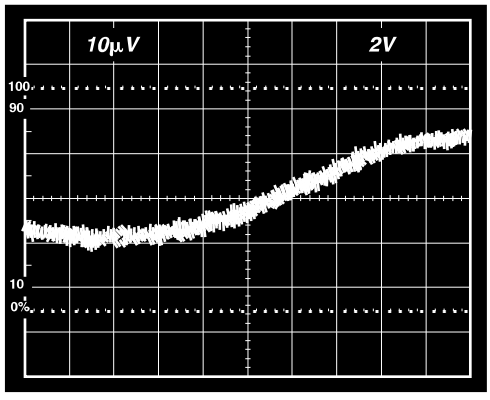

Figure 32. Gain Nonlinearity, G = 1, R_L = 10 kΩ (10 µV = 1 ppm)

PIC18F2455/2550/4455/4550
Data Sheet

28/40/44-Pin, High-Performance, Enhanced Flash, USB Microcontrollers with nanoWatt Technology

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

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QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
ISO/TS 16949:2002

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PIC18F2455/2550/4455/4550

28/40/44-Pin, High-Performance, Enhanced Flash, USB Microcontrollers with nanoWatt Technology

Universal Serial Bus Features:

- USB V2.0 Compliant
- Low Speed (1.5 Mb/s) and Full Speed (12 Mb/s)
- Supports Control, Interrupt, Isochronous and Bulk Transfers
- Supports up to 32 Endpoints (16 bidirectional)
- 1-Kbyte Dual Access RAM for USB
- On-Chip USB Transceiver with On-Chip Voltage Regulator
- Interface for Off-Chip USB Transceiver
- Streaming Parallel Port (SPP) for USB streaming transfers (40/44-pin devices only)

Power-Managed Modes:

- Run: CPU on, peripherals on
- Idle: CPU off, peripherals on
- Sleep: CPU off, peripherals off
- Idle mode currents down to 5.8 μA typical
- Sleep mode currents down to 0.1 μA typical
- Timer1 Oscillator: 1.1 μA typical, 32 kHz, 2V
- Watchdog Timer: 2.1 μA typical
- Two-Speed Oscillator Start-up

Flexible Oscillator Structure:

- Four Crystal modes, including High Precision PLL for USB
- Two External Clock modes, up to 48 MHz
- Internal Oscillator Block:
  - 8 user-selectable frequencies, from 31 kHz to 8 MHz
  - User-tunable to compensate for frequency drift
- Secondary Oscillator using Timer1 @ 32 kHz
- Dual Oscillator options allow microcontroller and USB module to run at different clock speeds
- Fail-Safe Clock Monitor:
  - Allows for safe shutdown if any clock stops

Peripheral Highlights:

- High-Current Sink/Source: 25 mA/25 mA
- Three External Interrupts
- Four Timer modules (Timer0 to Timer3)
- Up to 2 Capture/Compare/PWM (CCP) modules:
  - Capture is 16-bit, max. resolution 5.2 ns (TCY/16)
  - Compare is 16-bit, max. resolution 83.3 ns (TCY)
  - PWM output: PWM resolution is 1 to 10-bit
- Enhanced Capture/Compare/PWM (ECCP) module:
  - Multiple output modes
  - Selectable polarity
  - Programmable dead time
  - Auto-shutdown and auto-restart
- Enhanced USART module:
  - LIN bus support
- Master Synchronous Serial Port (MSSP) module supporting 3-wire SPI (all 4 modes) and I^2C™ Master and Slave modes
- 10-bit, up to 13-channel Analog-to-Digital Converter module (A/D) with Programmable Acquisition Time
- Dual Analog Comparators with Input Multiplexing

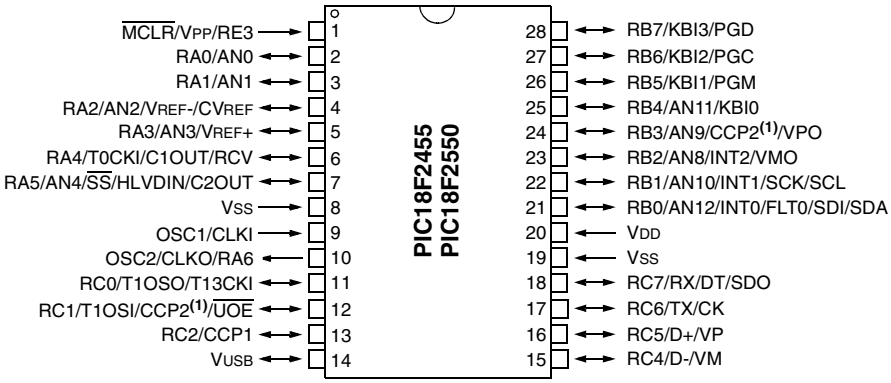
Special Microcontroller Features:

- C Compiler Optimized Architecture with optional Extended Instruction Set
- 100,000 Erase/Write Cycle Enhanced Flash Program Memory typical
- 1,000,000 Erase/Write Cycle Data EEPROM Memory typical
- Flash/Data EEPROM Retention: > 40 years
- Self-Programmable under Software Control
- Priority Levels for Interrupts
- 8 x 8 Single-Cycle Hardware Multiplier
- Extended Watchdog Timer (WDT):
  - Programmable period from 41 ms to 131s
- Programmable Code Protection
- Single-Supply 5V In-Circuit Serial Programming™ (ICSP™) via two pins
- In-Circuit Debug (ICD) via two pins
- Optional dedicated ICD/ICSP port (44-pin devices only)
- Wide Operating Voltage Range (2.0V to 5.5V)

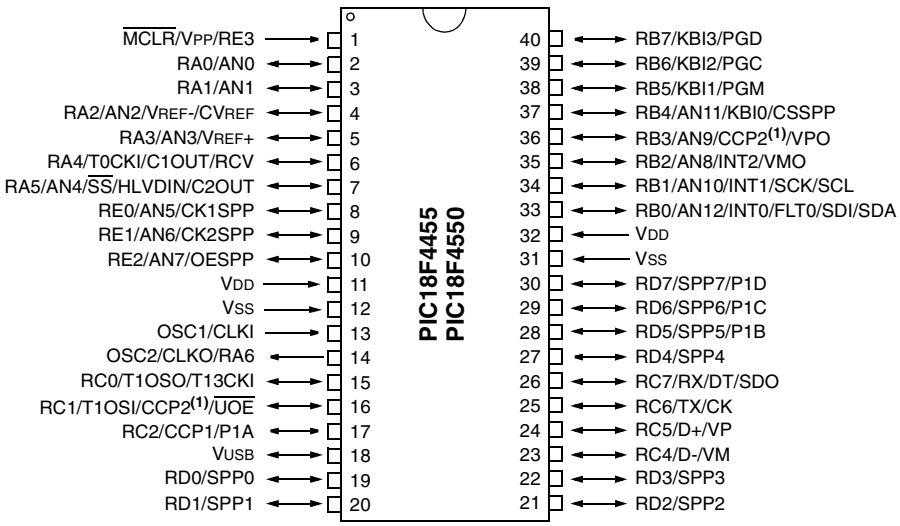
Device	Program Memory		Data Memory		I/O	10-Bit A/D (ch)	CCP/ECCP (PWM)	SPP	MSSP		EAUSART	Comparators	Timers 8/16-Bit
	Flash (bytes)	# Single-Word Instructions	SRAM (bytes)	EEPROM (bytes)					SPI	Master I^2C™			
PIC18F2455	24K	12288	2048	256	24	10	2/0	No	Y	Y	1	2	1/3
PIC18F2550	32K	16384	2048	256	24	10	2/0	No	Y	Y	1	2	1/3
PIC18F4455	24K	12288	2048	256	35	13	1/1	Yes	Y	Y	1	2	1/3
PIC18F4550	32K	16384	2048	256	35	13	1/1	Yes	Y	Y	1	2	1/3

Pin Diagrams

28-Pin PDIP, SOIC



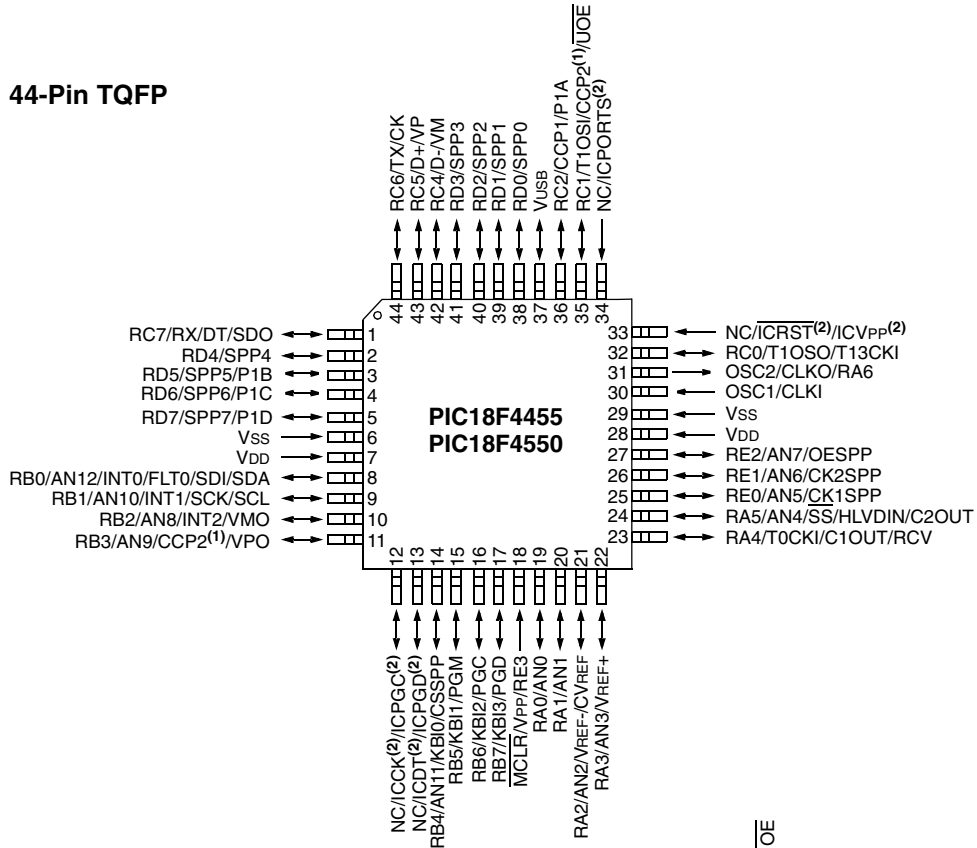
40-Pin PDIP



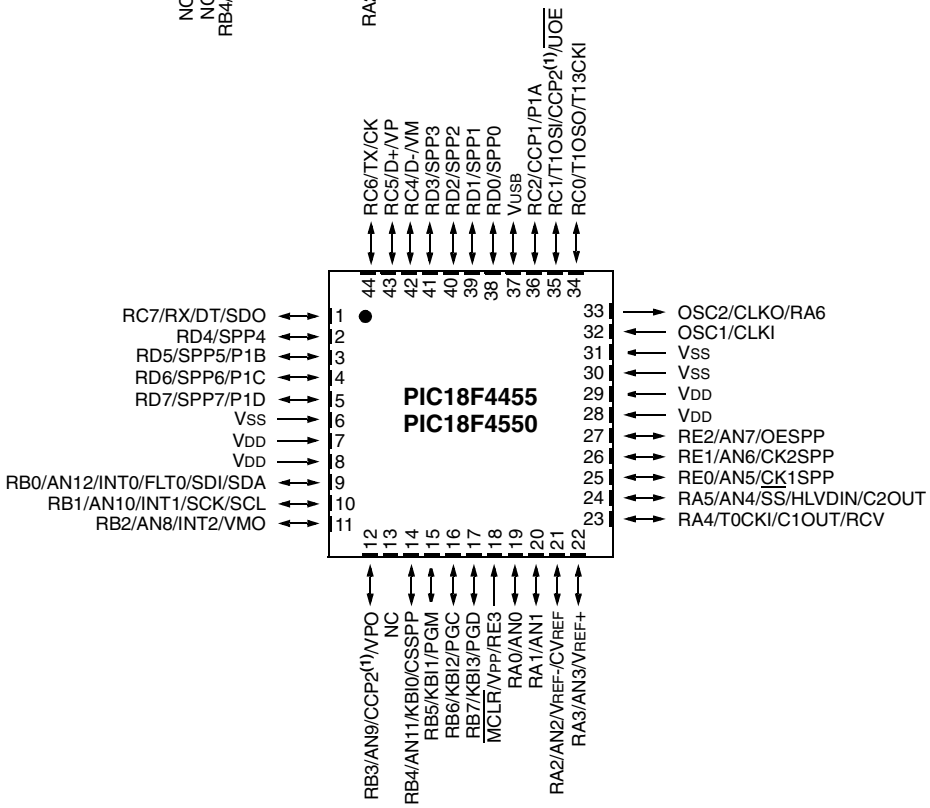
Note 1: RB3 is the alternate pin for CCP2 multiplexing.

Pin Diagrams (Continued)

44-Pin TQFP



44-Pin QFN



Note 1: RB3 is the alternate pin for CCP2 multiplexing.

2: Special ICPORTS features available in select circumstances. See **Section 25.9 "Special ICPORT Features (Designated Packages Only)"** for more information.

Table of Contents

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To determine if an errata sheet exists for a particular device, please check with one of the following:

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NOTES:

1.0 DEVICE OVERVIEW

This document contains device-specific information for the following devices:

- PIC18F2455
- PIC18F2550
- PIC18F4455
- PIC18F4550
- PIC18LF2455
- PIC18LF2550
- PIC18LF4455
- PIC18LF4550

This family of devices offers the advantages of all PIC18 microcontrollers – namely, high computational performance at an economical price – with the addition of high endurance, Enhanced Flash program memory. In addition to these features, the PIC18F2455/2550/4455/4550 family introduces design enhancements that make these microcontrollers a logical choice for many high-performance, power sensitive applications.

1.1 New Core Features

1.1.1 nanoWatt TECHNOLOGY

All of the devices in the PIC18F2455/2550/4455/4550 family incorporate a range of features that can significantly reduce power consumption during operation. Key items include:

- **Alternate Run Modes:** By clocking the controller from the Timer1 source or the internal oscillator block, power consumption during code execution can be reduced by as much as 90%.
- **Multiple Idle Modes:** The controller can also run with its CPU core disabled but the peripherals still active. In these states, power consumption can be reduced even further, to as little as 4% of normal operation requirements.
- **On-the-Fly Mode Switching:** The power-managed modes are invoked by user code during operation, allowing the user to incorporate power-saving ideas into their application's software design.
- **Low Consumption in Key Modules:** The power requirements for both Timer1 and the Watchdog Timer are minimized. See **Section 28.0 "Electrical Characteristics"** for values.

1.1.2 UNIVERSAL SERIAL BUS (USB)

Devices in the PIC18F2455/2550/4455/4550 family incorporate a fully featured Universal Serial Bus communications module that is compliant with the USB Specification Revision 2.0. The module supports both low-speed and full-speed communication for all supported data transfer types. It also incorporates its own on-chip transceiver and 3.3V regulator and supports the use of external transceivers and voltage regulators.

1.1.3 MULTIPLE OSCILLATOR OPTIONS AND FEATURES

All of the devices in the PIC18F2455/2550/4455/4550 family offer twelve different oscillator options, allowing users a wide range of choices in developing application hardware. These include:

- Four Crystal modes using crystals or ceramic resonators.
- Four External Clock modes, offering the option of using two pins (oscillator input and a divide-by-4 clock output) or one pin (oscillator input, with the second pin reassigned as general I/O).
- An internal oscillator block which provides an 8 MHz clock (±2% accuracy) and an INTRC source (approximately 31 kHz, stable over temperature and V_{DD}), as well as a range of 6 user-selectable clock frequencies, between 125 kHz to 4 MHz, for a total of 8 clock frequencies. This option frees an oscillator pin for use as an additional general purpose I/O.
- A Phase Lock Loop (PLL) frequency multiplier, available to both the High-Speed Crystal and External Oscillator modes, which allows a wide range of clock speeds from 4 MHz to 48 MHz.
- Asynchronous dual clock operation, allowing the USB module to run from a high-frequency oscillator while the rest of the microcontroller is clocked from an internal low-power oscillator.

Besides its availability as a clock source, the internal oscillator block provides a stable reference source that gives the family additional features for robust operation:

- **Fail-Safe Clock Monitor:** This option constantly monitors the main clock source against a reference signal provided by the internal oscillator. If a clock failure occurs, the controller is switched to the internal oscillator block, allowing for continued low-speed operation or a safe application shutdown.
- **Two-Speed Start-up:** This option allows the internal oscillator to serve as the clock source from Power-on Reset, or wake-up from Sleep mode, until the primary clock source is available.

20.0 ENHANCED UNIVERSAL SYNCHRONOUS ASYNCHRONOUS RECEIVER TRANSMITTER (EUSART)

The Enhanced Universal Synchronous Asynchronous Receiver Transmitter (EUSART) module is one of the two serial I/O modules. (Generically, the USART is also known as a Serial Communications Interface or SCI.) The EUSART can be configured as a full-duplex asynchronous system that can communicate with peripheral devices, such as CRT terminals and personal computers. It can also be configured as a half-duplex synchronous system that can communicate with peripheral devices, such as A/D or D/A integrated circuits, serial EEPROMs, etc.

The Enhanced USART module implements additional features, including automatic baud rate detection and calibration, automatic wake-up on Sync Break reception and 12-bit Break character transmit. These make it ideally suited for use in Local Interconnect Network bus (LIN bus) systems.

The EUSART can be configured in the following modes:

- Asynchronous (full-duplex) with:
  - Auto-wake-up on Break signal
  - Auto-baud calibration
  - 12-bit Break character transmission
- Synchronous – Master (half-duplex) with selectable clock polarity
- Synchronous – Slave (half-duplex) with selectable clock polarity

The pins of the Enhanced USART are multiplexed with PORTC. In order to configure RC6/TX/CK and RC7/RX/DT/SDO as an EUSART:

- bit SPEN (RCSTA<7>) must be set (= 1)
- bit TRISC<7> must be set (= 1)
- bit TRISC<6> must be set (= 1)

Note:	The EUSART control will automatically reconfigure the pin from input to output as needed.

The operation of the Enhanced USART module is controlled through three registers:

- Transmit Status and Control (TXSTA)
- Receive Status and Control (RCSTA)
- Baud Rate Control (BAUDCON)

These are detailed on the following pages in Register 20-1, Register 20-2 and Register 20-3, respectively.

REGISTER 20-1: TXSTA: TRANSMIT STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-1	R/W-0
CSRC	TX9	TXEN(1)	SYNC	SENDB	BRGH	TRMT	TX9D
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **CSRC:** Clock Source Select bit
Asynchronous mode:
Don't care.
Synchronous mode:
1 = Master mode (clock generated internally from BRG)
0 = Slave mode (clock from external source)

bit 6 **TX9:** 9-Bit Transmit Enable bit
1 = Selects 9-bit transmission
0 = Selects 8-bit transmission

bit 5 **TXEN:** Transmit Enable bit(1)
1 = Transmit enabled
0 = Transmit disabled

bit 4 **SYNC:** EUSART Mode Select bit
1 = Synchronous mode
0 = Asynchronous mode

bit 3 **SENDB:** Send Break Character bit
Asynchronous mode:
1 = Send Sync Break on next transmission (cleared by hardware upon completion)
0 = Sync Break transmission completed
Synchronous mode:
Don't care.

bit 2 **BRGH:** High Baud Rate Select bit
Asynchronous mode:
1 = High speed
0 = Low speed
Synchronous mode:
Unused in this mode.

bit 1 **TRMT:** Transmit Shift Register Status bit
1 = TSR empty
0 = TSR full

bit 0 **TX9D:** 9th bit of Transmit Data
Can be address/data bit or a parity bit.

Note 1: SREN/CREN overrides TXEN in Sync mode with the exception that SREN has no effect in Synchronous Slave mode.

REGISTER 20-2: RCSTA: RECEIVE STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-x
SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **SPEN:** Serial Port Enable bit
1 = Serial port enabled (configures RX/DT and TX/CK pins as serial port pins)
0 = Serial port disabled (held in Reset)

bit 6 **RX9:** 9-Bit Receive Enable bit
1 = Selects 9-bit reception
0 = Selects 8-bit reception

bit 5 **SREN:** Single Receive Enable bit
Asynchronous mode:
Don't care.
Synchronous mode – Master:
1 = Enables single receive
0 = Disables single receive
This bit is cleared after reception is complete.
Synchronous mode – Slave:
Don't care.

bit 4 **CREN:** Continuous Receive Enable bit
Asynchronous mode:
1 = Enables receiver
0 = Disables receiver
Synchronous mode:
1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)
0 = Disables continuous receive

bit 3 **ADDEN:** Address Detect Enable bit
Asynchronous mode 9-bit (RX9 = 1):
1 = Enables address detection, enables interrupt and loads the receive buffer when RSR<8> is set
0 = Disables address detection, all bytes are received and ninth bit can be used as parity bit
Asynchronous mode 9-bit (RX9 = 0):
Don't care.

bit 2 **FERR:** Framing Error bit
1 = Framing error (can be updated by reading RCREG register and receiving next valid byte)
0 = No framing error

bit 1 **OERR:** Overrun Error bit
1 = Overrun error (can be cleared by clearing bit CREN)
0 = No overrun error

bit 0 **RX9D:** 9th bit of Received Data
This can be address/data bit or a parity bit and must be calculated by user firmware.

REGISTER 20-3: BAUDCON: BAUD RATE CONTROL REGISTER

R/W-0	R-1	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
ABDOVF	RCIDL	RXDTP	TXCKP	BRG16	—	WUE	ABDEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **ABDOVF**: Auto-Baud Acquisition Rollover Status bit
1 = A BRG rollover has occurred during Auto-Baud Rate Detect mode (must be cleared in software)
0 = No BRG rollover has occurred

bit 6 **RCIDL**: Receive Operation Idle Status bit
1 = Receive operation is Idle
0 = Receive operation is active

bit 5 **RXDTP**: Received Data Polarity Select bit
Asynchronous mode:
1 = RX data is inverted
0 = RX data received is not inverted
Synchronous modes:
1 = CK clocks are inverted
0 = CK clocks are not inverted

bit 4 **TXCKP**: Clock and Data Polarity Select bit
Asynchronous mode:
1 = TX data is inverted
0 = TX data is not inverted
Synchronous modes:
1 = CK clocks are inverted
0 = CK clocks are not inverted

bit 3 **BRG16:** 16-Bit Baud Rate Register Enable bit
1 = 16-bit Baud Rate Generator – SPBRGH and SPBRG
0 = 8-bit Baud Rate Generator – SPBRG only (Compatible mode), SPBRGH value ignored

bit 2 **Unimplemented:** Read as '0'

bit 1 **WUE:** Wake-up Enable bit
Asynchronous mode:
1 = EUSART will continue to sample the RX pin – interrupt generated on falling edge; bit cleared in hardware on following rising edge
0 = RX pin not monitored or rising edge detected
Synchronous mode:
Unused in this mode.

bit 0 **ABDEN**: Auto-Baud Detect Enable bit
Asynchronous mode:
1 = Enable baud rate measurement on the next character. Requires reception of a Sync field (55h); cleared in hardware upon completion.
0 = Baud rate measurement disabled or completed
Synchronous mode:
Unused in this mode.

20.1 Baud Rate Generator (BRG)

The BRG is a dedicated 8-bit, or 16-bit, generator that supports both the Asynchronous and Synchronous modes of the EUSART. By default, the BRG operates in 8-bit mode. Setting the BRG16 bit (BAUDCON<3>) selects 16-bit mode.

The SPBRGH:SPBRG register pair controls the period of a free-running timer. In Asynchronous mode, bits BRGH (TXSTA<2>) and BRG16 (BAUDCON<3>) also control the baud rate. In Synchronous mode, BRGH is ignored. Table 20-1 shows the formula for computation of the baud rate for different EUSART modes which only apply in Master mode (internally generated clock).

Given the desired baud rate and FOSC, the nearest integer value for the SPBRGH:SPBRG registers can be calculated using the formulas in Table 20-1. From this, the error in baud rate can be determined. An example calculation is shown in Example 20-1. Typical baud rates and error values for the various Asynchronous modes are shown in Table 20-2. It may be advantageous to use the high baud rate (BRGH = 1), or the 16-bit BRG to reduce the baud rate error, or achieve a slow baud rate for a fast oscillator frequency.

Writing a new value to the SPBRGH:SPBRG registers causes the BRG timer to be reset (or cleared). This ensures the BRG does not wait for a timer overflow before outputting the new baud rate.

20.1.1 OPERATION IN POWER-MANAGED MODES

The device clock is used to generate the desired baud rate. When one of the power-managed modes is entered, the new clock source may be operating at a different frequency. This may require an adjustment to the value in the SPBRG register pair.

20.1.2 SAMPLING

The data on the RX pin is sampled three times by a majority detect circuit to determine if a high or a low level is present at the RX pin.

TABLE 20-1: BAUD RATE FORMULAS

Configuration Bits			BRG/EUSART Mode	Baud Rate Formula
SYNC	BRG16	BRGH		
0	0	0	8-bit/Asynchronous	FOSC/[64 (n + 1)]
0	0	1	8-bit/Asynchronous	FOSC/[16 (n + 1)]
0	1	0	16-bit/Asynchronous	
0	1	1	16-bit/Asynchronous	FOSC/[4 (n + 1)]
1	0	x	8-bit/Synchronous	
1	1	x	16-bit/Synchronous	

Legend: x = Don't care, n = value of SPBRGH:SPBRG register pair

EXAMPLE 20-1: CALCULATING BAUD RATE ERROR

For a device with FOSC of 16 MHz, desired baud rate of 9600, Asynchronous mode, 8-bit BRG:

Desired Baud Rate = FOSC/(64 ([SPBRGH:SPBRG] + 1))

Solving for SPBRGH:SPBRG:

X = ((FOSC/Desired Baud Rate)/64) – 1
= ((16000000/9600)/64) – 1
= [25.042] = 25

Calculated Baud Rate = 16000000/(64 (25 + 1))
= 9615

Error = (Calculated Baud Rate – Desired Baud Rate)/Desired Baud Rate
= (9615 – 9600)/9600 = 0.16%

TABLE 20-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	53
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	53
BAUDCON	ABDOVF	RCIDL	RXDTP	TXCKP	BRG16	—	WUE	ABDEN	53
SPBRGH	EUSART Baud Rate Generator Register High Byte								53
SPBRG	EUSART Baud Rate Generator Register Low Byte								53

Legend: — = unimplemented, read as '0'. Shaded cells are not used by the BRG.

TABLE 20-3: BAUD RATES FOR ASYNCHRONOUS MODES

BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 0											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	—	—	—	—	—	—	—	—	—	—	—	—
1.2	—	—	—	1.221	1.73	255	1.202	0.16	129	1201	-0.16	103
2.4	2.441	1.73	255	2.404	0.16	129	2.404	0.16	64	2403	-0.16	51
9.6	9.615	0.16	64	9.766	1.73	31	9.766	1.73	15	9615	-0.16	12
19.2	19.531	1.73	31	19.531	1.73	15	19.531	1.73	7	—	—	—
57.6	56.818	-1.36	10	62.500	8.51	4	52.083	-9.58	2	—	—	—
115.2	125.000	8.51	4	104.167	-9.58	2	78.125	-32.18	1	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 0								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.16	207	300	-0.16	103	300	-0.16	51
1.2	1.202	0.16	51	1201	-0.16	25	1201	-0.16	12
2.4	2.404	0.16	25	2403	-0.16	12	—	—	—
9.6	8.929	-6.99	6	—	—	—	—	—	—
19.2	20.833	8.51	2	—	—	—	—	—	—
57.6	62.500	8.51	0	—	—	—	—	—	—
115.2	62.500	-45.75	0	—	—	—	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 0											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	—	—	—	—	—	—	—	—	—	—	—	—
1.2	—	—	—	—	—	—	—	—	—	—	—	—
2.4	—	—	—	—	—	—	2.441	1.73	255	2403	-0.16	207
9.6	9.766	1.73	255	9.615	0.16	129	9.615	0.16	64	9615	-0.16	51
19.2	19.231	0.16	129	19.231	0.16	64	19.531	1.73	31	19230	-0.16	25
57.6	58.140	0.94	42	56.818	-1.36	21	56.818	-1.36	10	55555	3.55	8
115.2	113.636	-1.36	21	113.636	-1.36	10	125.000	8.51	4	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 0								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	—	—	—	—	—	—	300	-0.16	207
1.2	1.202	0.16	207	1201	-0.16	103	1201	-0.16	51
2.4	2.404	0.16	103	2403	-0.16	51	2403	-0.16	25
9.6	9.615	0.16	25	9615	-0.16	12	—	—	—
19.2	19.231	0.16	12	—	—	—	—	—	—
57.6	62.500	8.51	3	—	—	—	—	—	—
115.2	125.000	8.51	1	—	—	—	—	—	—

TABLE 20-3: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 1											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.00	8332	0.300	0.02	4165	0.300	0.02	2082	300	-0.04	1665
1.2	1.200	0.02	2082	1.200	-0.03	1041	1.200	-0.03	520	1201	-0.16	415
2.4	2.402	0.06	1040	2.399	-0.03	520	2.404	0.16	259	2403	-0.16	207
9.6	9.615	0.16	259	9.615	0.16	129	9.615	0.16	64	9615	-0.16	51
19.2	19.231	0.16	129	19.231	0.16	64	19.531	1.73	31	19230	-0.16	25
57.6	58.140	0.94	42	56.818	-1.36	21	56.818	-1.36	10	55555	3.55	8
115.2	113.636	-1.36	21	113.636	-1.36	10	125.000	8.51	4	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 0, BRG16 = 1								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.04	832	300	-0.16	415	300	-0.16	207
1.2	1.202	0.16	207	1201	-0.16	103	1201	-0.16	51
2.4	2.404	0.16	103	2403	-0.16	51	2403	-0.16	25
9.6	9.615	0.16	25	9615	-0.16	12	—	—	—
19.2	19.231	0.16	12	—	—	—	—	—	—
57.6	62.500	8.51	3	—	—	—	—	—	—
115.2	125.000	8.51	1	—	—	—	—	—	—

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.00	33332	0.300	0.00	16665	0.300	0.00	8332	300	-0.01	6665
1.2	1.200	0.00	8332	1.200	0.02	4165	1.200	0.02	2082	1200	-0.04	1665
2.4	2.400	0.02	4165	2.400	0.02	2082	2.402	0.06	1040	2400	-0.04	832
9.6	9.606	0.06	1040	9.596	-0.03	520	9.615	0.16	259	9615	-0.16	207
19.2	19.193	-0.03	520	19.231	0.16	259	19.231	0.16	129	19230	-0.16	103
57.6	57.803	0.35	172	57.471	-0.22	86	58.140	0.94	42	57142	0.79	34
115.2	114.943	-0.22	86	116.279	0.94	42	113.636	-1.36	21	117647	-2.12	16

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.01	3332	300	-0.04	1665	300	-0.04	832
1.2	1.200	0.04	832	1201	-0.16	415	1201	-0.16	207
2.4	2.404	0.16	415	2403	-0.16	207	2403	-0.16	103
9.6	9.615	0.16	103	9615	-0.16	51	9615	-0.16	25
19.2	19.231	0.16	51	19230	-0.16	25	19230	-0.16	12
57.6	58.824	2.12	16	55555	3.55	8	—	—	—
115.2	111.111	-3.55	8	—	—	—	—	—	—

20.1.3 AUTO-BAUD RATE DETECT

The Enhanced USART module supports the automatic detection and calibration of baud rate. This feature is active only in Asynchronous mode and while the WUE bit is clear.

The automatic baud rate measurement sequence (Figure 20-1) begins whenever a Start bit is received and the ABDEN bit is set. The calculation is self-averaging.

In the Auto-Baud Rate Detect (ABD) mode, the clock to the BRG is reversed. Rather than the BRG clocking the incoming RX signal, the RX signal is timing the BRG. In ABD mode, the internal Baud Rate Generator is used as a counter to time the bit period of the incoming serial byte stream.

Once the ABDEN bit is set, the state machine will clear the BRG and look for a Start bit. The Auto-Baud Rate Detect must receive a byte with the value 55h (ASCII "U", which is also the LIN bus Sync character) in order to calculate the proper bit rate. The measurement is taken over both a low and a high bit time in order to minimize any effects caused by asymmetry of the incoming signal. After a Start bit, the SPBRG begins counting up, using the preselected clock source on the first rising edge of RX. After eight bits on the RX pin, or the fifth rising edge, an accumulated value totalling the proper BRG period is left in the SPBRGH:SPBRG register pair. Once the 5th edge is seen (this should correspond to the Stop bit), the ABDEN bit is automatically cleared.

If a rollover of the BRG occurs (an overflow from FFFFh to 0000h), the event is trapped by the ABDOVF status bit (BAUDCON<7>). It is set in hardware by BRG rollovers and can be set or cleared by the user in software. ABD mode remains active after rollover events and the ABDEN bit remains set (Figure 20-2).

While calibrating the baud rate period, the BRG registers are clocked at 1/8th the preconfigured clock rate. Note that the BRG clock will be configured by the BRG16 and BRGH bits. Independent of the BRG16 bit setting, both the SPBRG and SPBRGH will be used as a 16-bit counter. This allows the user to verify that no carry occurred for 8-bit modes by checking for 00h in the SPBRGH register. Refer to Table 20-4 for counter clock rates to the BRG.

While the ABD sequence takes place, the EUSART state machine is held in Idle. The RCIF interrupt is set once the fifth rising edge on RX is detected. The value in the RCREG needs to be read to clear the RCIF interrupt. The contents of RCREG should be discarded.

Note 1: If the WUE bit is set with the ABDEN bit, Auto-Baud Rate Detection will occur on the byte *following* the Break character.

2: It is up to the user to determine that the incoming character baud rate is within the range of the selected BRG clock source. Some combinations of oscillator frequency and EUSART baud rates are not possible due to bit error rates. Overall system timing and communication baud rates must be taken into consideration when using the Auto-Baud Rate Detection feature.

TABLE 20-4: BRG COUNTER CLOCK RATES

BRG16	BRGH	BRG Counter Clock
0	0	FOSC/512
0	1	FOSC/128
1	0	FOSC/128
1	1	FOSC/32

Note: During the ABD sequence, SPBRG and SPBRGH are both used as a 16-bit counter, independent of the BRG16 setting.

20.1.3.1 ABD and EUSART Transmission

Since the BRG clock is reversed during ABD acquisition, the EUSART transmitter cannot be used during ABD. This means that whenever the ABDEN bit is set, TXREG cannot be written to. Users should also ensure that ABDEN does not become set during a transmit sequence. Failing to do this may result in unpredictable EUSART operation.

21.0 10-BIT ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The Analog-to-Digital (A/D) converter module has 10 inputs for the 28-pin devices and 13 for the 40/44-pin devices. This module allows conversion of an analog input signal to a corresponding 10-bit digital number.

The module has five registers:

- A/D Result High Register (ADRESH)
- A/D Result Low Register (ADRESL)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)
- A/D Control Register 2 (ADCON2)

The ADCON0 register, shown in Register 21-1, controls the operation of the A/D module. The ADCON1 register, shown in Register 21-2, configures the functions of the port pins. The ADCON2 register, shown in Register 21-3, configures the A/D clock source, programmed acquisition time and justification.

REGISTER 21-1: ADCON0: A/D CONTROL REGISTER 0

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5-2 **CHS3:CHS0:** Analog Channel Select bits
0000 = Channel 0 (AN0)
0001 = Channel 1 (AN1)
0010 = Channel 2 (AN2)
0011 = Channel 3 (AN3)
0100 = Channel 4 (AN4)
0101 = Channel 5 (AN5)(1,2)
0110 = Channel 6 (AN6)(1,2)
0111 = Channel 7 (AN7)(1,2)
1000 = Channel 8 (AN8)
1001 = Channel 9 (AN9)
1010 = Channel 10 (AN10)
1011 = Channel 11 (AN11)
1100 = Channel 12 (AN12)
1101 = Unimplemented(2)
1110 = Unimplemented(2)
1111 = Unimplemented(2)

bit 1 **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit
When ADON = 1:
1 = A/D conversion in progress
0 = A/D Idle

bit 0 **ADON:** A/D On bit
1 = A/D converter module is enabled
0 = A/D converter module is disabled

Note 1: These channels are not implemented on 28-pin devices.
2: Performing a conversion on unimplemented channels will return a floating input measurement.

REGISTER 21-2: ADCON1: A/D CONTROL REGISTER 1

U-0	U-0	R/W-0	R/W-0	R/W-0(1)	R/W(1)	R/W(1)	R/W(1)
—	—	VCFG0	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5 **VCFG0:** Voltage Reference Configuration bit (V_{REF-} source)
1 = V_{REF-} (AN2)
0 = V_{SS}

bit 4 **VCFG0:** Voltage Reference Configuration bit (V_{REF+} source)
1 = V_{REF+} (AN3)
0 = V_{DD}

bit 3-0 **PCFG3:PCFG0:** A/D Port Configuration Control bits:

PCFG3: PCFG0	AN12	AN11	AN10	AN9	AN8	AN7(2)	AN6(2)	AN5(2)	AN4	AN3	AN2	AN1	AN0
0000(1)	A	A	A	A	A	A	A	A	A	A	A	A	A
0001	A	A	A	A	A	A	A	A	A	A	A	A	A
0010	A	A	A	A	A	A	A	A	A	A	A	A	A
0011	D	A	A	A	A	A	A	A	A	A	A	A	A
0100	D	D	A	A	A	A	A	A	A	A	A	A	A
0101	D	D	D	A	A	A	A	A	A	A	A	A	A
0110	D	D	D	D	A	A	A	A	A	A	A	A	A
0111(1)	D	D	D	D	D	A	A	A	A	A	A	A	A
1000	D	D	D	D	D	D	A	A	A	A	A	A	A
1001	D	D	D	D	D	D	D	A	A	A	A	A	A
1010	D	D	D	D	D	D	D	D	A	A	A	A	A
1011	D	D	D	D	D	D	D	D	D	A	A	A	A
1100	D	D	D	D	D	D	D	D	D	D	A	A	A
1101	D	D	D	D	D	D	D	D	D	D	D	A	A
1110	D	D	D	D	D	D	D	D	D	D	D	D	A
1111	D	D	D	D	D	D	D	D	D	D	D	D	D

A = Analog input D = Digital I/O

Note 1: The POR value of the PCFG bits depends on the value of the PBADEN Configuration bit. When PBADEN = 1, PCFG<3:0> = 0000; when PBADEN = 0, PCFG<3:0> = 0111.

2: AN5 through AN7 are available only on 40/44-pin devices.

REGISTER 21-3: ADCON2: A/D CONTROL REGISTER 2

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADFM	—	ACQT2	ACQT1	ACQT0	ADCS2	ADCS1	ADCS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **ADFM:** A/D Result Format Select bit
1 = Right justified
0 = Left justified

bit 6 **Unimplemented:** Read as '0'

bit 5-3 **ACQT2:ACQT0:** A/D Acquisition Time Select bits
111 = 20 TAD
110 = 16 TAD
101 = 12 TAD
100 = 8 TAD
011 = 6 TAD
010 = 4 TAD
001 = 2 TAD
000 = 0 TAD(1)

bit 2-0 **ADCS2:ADCS0:** A/D Conversion Clock Select bits
111 = FRC (clock derived from A/D RC oscillator)(1)
110 = FOSC/64
101 = FOSC/16
100 = FOSC/4
011 = FRC (clock derived from A/D RC oscillator)(1)
010 = FOSC/32
001 = FOSC/8
000 = FOSC/2

Note 1: If the A/D FRC clock source is selected, a delay of one TCY (instruction cycle) is added before the A/D clock starts. This allows the SLEEP instruction to be executed before starting a conversion.

The analog reference voltage is software selectable to either the device's positive and negative supply voltage (V_{DD} and V_{SS}) or the voltage level on the RA3/AN3/V_{REF+} and RA2/AN2/V_{REF-}/CV_{REF} pins.

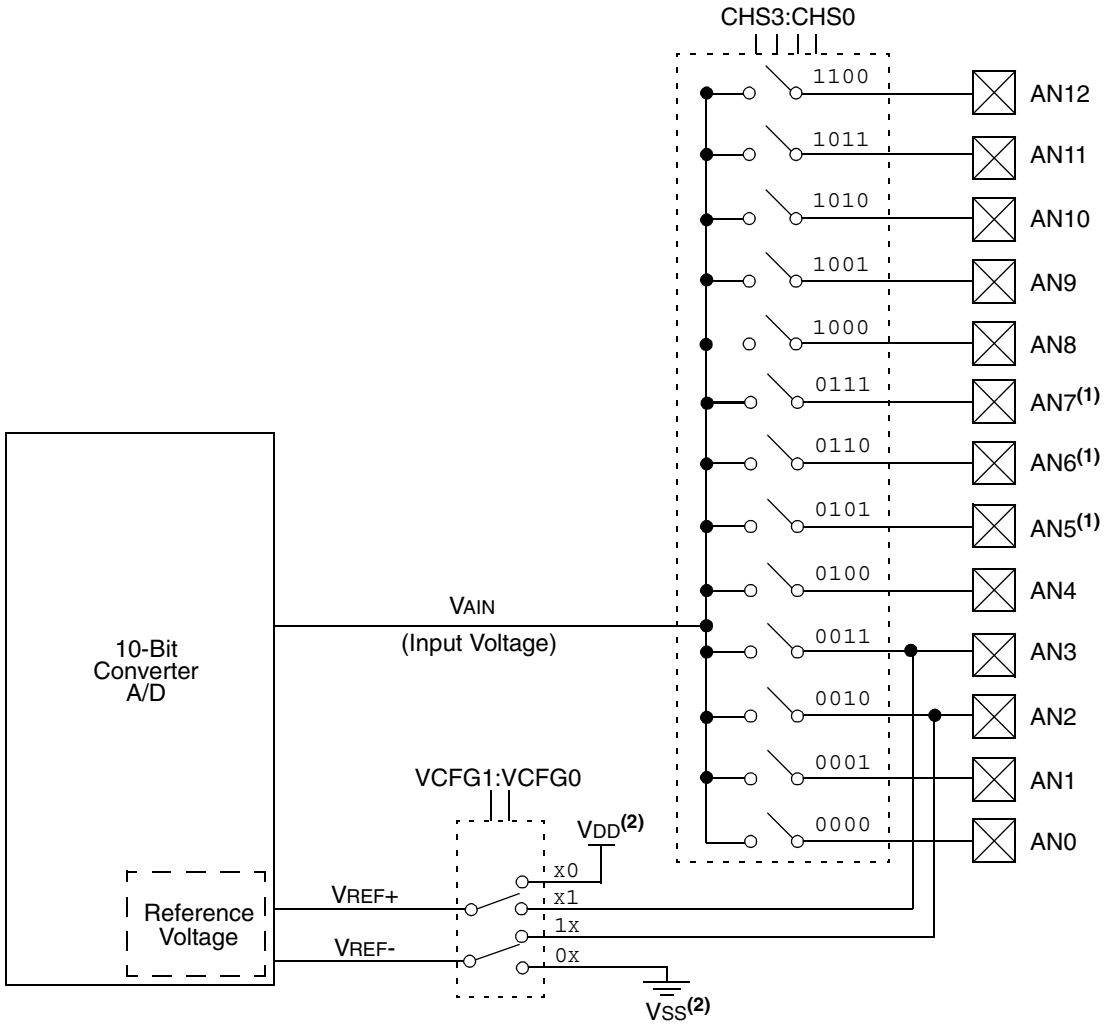
The A/D converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

The output of the sample and hold is the input into the converter, which generates the result via successive approximation.

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off and any conversion in progress is aborted.

Each port pin associated with the A/D converter can be configured as an analog input or as a digital I/O. The ADRESH and ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRESH:ADRESL register pair, the GO/$\overline{\text{DONE}}$ bit (ADCON0 register) is cleared and A/D Interrupt Flag bit, ADIF, is set. The block diagram of the A/D module is shown in Figure 21-1.

FIGURE 21-1: A/D BLOCK DIAGRAM



Note 1: Channels AN5 through AN7 are not available on 28-pin devices.

2: I/O pins have diode protection to V_{DD} and V_{SS}.

The value in the ADRESH:ADRESL registers is not modified for a Power-on Reset. The ADRESH:ADRESL registers will contain unknown data after a Power-on Reset.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see **Section 21.1 "A/D Acquisition Requirements"**. After this acquisition time has elapsed, the A/D conversion can be started. An acquisition time can be programmed to occur between setting the GO/DONE bit and the actual start of the conversion.

The following steps should be followed to perform an A/D conversion:

1. Configure the A/D module:
   - Configure analog pins, voltage reference and digital I/O (ADCON1)
   - Select A/D input channel (ADCON0)
   - Select A/D acquisition time (ADCON2)
   - Select A/D conversion clock (ADCON2)
   - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
   - Clear ADIF bit
   - Set ADIE bit
   - Set GIE bit
3. Wait the required acquisition time (if required).
4. Start conversion:
   - Set GO/DONE bit (ADCON0 register)
5. Wait for A/D conversion to complete, by either:
   - Polling for the GO/DONE bit to be cleared

   OR
   - Waiting for the A/D interrupt
6. Read A/D Result registers (ADRESH:ADRESL); clear bit ADIF, if required.
7. For next conversion, go to step 1 or step 2, as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 3 TAD is required before the next acquisition starts.

FIGURE 21-2: A/D TRANSFER FUNCTION

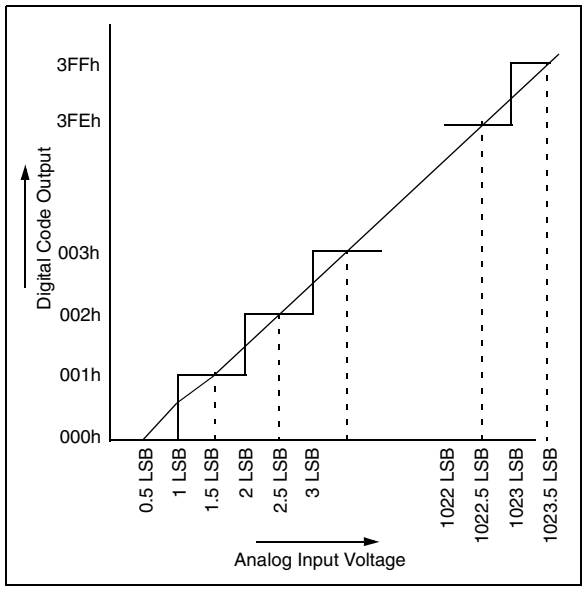
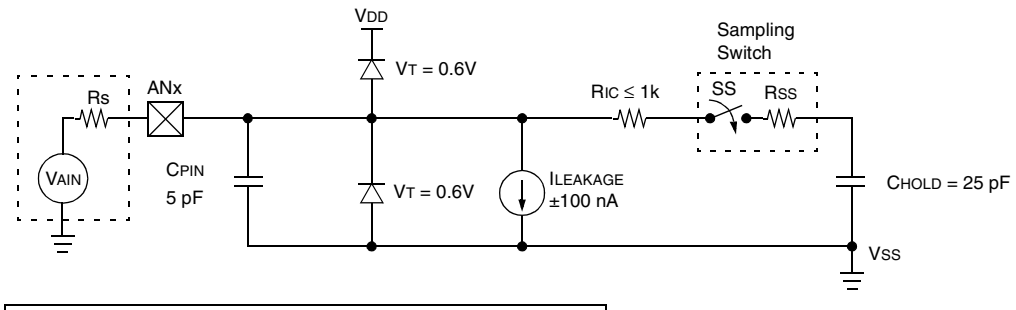
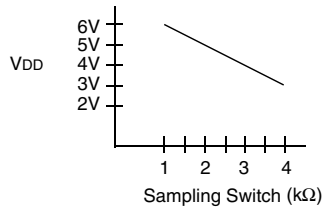


FIGURE 21-3: ANALOG INPUT MODEL



Legend:	CPIN	= Input Capacitance
	VT	= Threshold Voltage
	ILEAKAGE	= Leakage Current at the pin due to various junctions
	RIC	= Interconnect Resistance
	SS	= Sampling Switch
	CHOLD	= Sample/hold Capacitance (from DAC)
	RSS	= Sampling Switch Resistance



21.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 21-3. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 2.5 kΩ.** After the analog input channel is selected (changed), the channel must be sampled for at least the minimum acquisition time before starting a conversion.

Note:	When the conversion is started, the holding capacitor is disconnected from the input pin.

To calculate the minimum acquisition time, Equation 21-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

Example 21-3 shows the calculation of the minimum required acquisition time TACQ. This calculation is based on the following application system assumptions:

CHOLD	=	25 pF
Rs	=	2.5 kΩ
Conversion Error	≤	1/2 LSb
VDD	=	5V → RSS = 2 kΩ
Temperature	=	85°C (system max.)

EQUATION 21-1: ACQUISITION TIME

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Holding Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$

EQUATION 21-2: A/D MINIMUM CHARGING TIME

$$V_{HOLD} = (V_{REF} - (V_{REF}/2048)) \cdot (1 - e^{(-T_C/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$$
or
$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S) \ln(1/2048)$$

EQUATION 21-3: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$$T_{ACQ} = T_{AMP} + T_C + T_{COFF}$$
$$T_{AMP} = 0.2\ \mu s$$
$$T_{COFF} = (\text{Temp} - 25°C)(0.02\ \mu s/°C)$$
$$(85°C - 25°C)(0.02\ \mu s/°C)$$
$$1.2\ \mu s$$

Temperature coefficient is only required for temperatures > 25°C. Below 25°C, T_{COFF} = 0 ms.

$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S) \ln(1/2048)\ \mu s$$
$$-(25\ pF)\ (1\ k\Omega + 2\ k\Omega + 2.5\ k\Omega) \ln(0.0004883)\ \mu s$$
$$1.05\ \mu s$$

$$T_{ACQ} = 0.2\ \mu s + 1.05\ \mu s + 1.2\ \mu s$$
$$2.45\ \mu s$$

21.2 Selecting and Configuring Acquisition Time

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/DONE bit is set. It also gives users the option to use an automatically determined acquisition time.

Acquisition time may be set with the ACQT2:ACQT0 bits (ADCON2<5:3>) which provide a range of 2 to 20 TAD. When the GO/DONE bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there may be no need to wait for an acquisition time between selecting a channel and setting the GO/DONE bit.

Manual acquisition is selected when ACQT2:ACQT0 = 000. When the GO/DONE bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/DONE bit. This option is also the default Reset state of the ACQT2:ACQT0 bits and is compatible with devices that do not offer programmable acquisition times.

In either case, when the conversion is completed, the GO/DONE bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. If an acquisition time is programmed, there is nothing to indicate if the acquisition time has ended or if the conversion has begun.

21.3 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 11 TAD per 10-bit conversion. The source of the A/D conversion clock is software selectable. There are seven possible options for TAD:

- 2 TOSC
- 4 TOSC
- 8 TOSC
- 16 TOSC
- 32 TOSC
- 64 TOSC
- Internal RC Oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be as short as possible but greater than the minimum TAD (see parameter 130 in Table 28-29 for more information).

Table 21-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

TABLE 21-1: TAD vs. DEVICE OPERATING FREQUENCIES

AD Clock Source (TAD)		Maximum Device Frequency	
Operation	**ADCS2:ADCS0**	**PIC18FXXXX**	**PIC18LFXXXX(4)**
2 TOSC	000	2.86 MHz	1.43 MHz
4 TOSC	100	5.71 MHz	2.86 MHz
8 TOSC	001	11.43 MHz	5.72 MHz
16 TOSC	101	22.86 MHz	11.43 MHz
32 TOSC	010	45.71 MHz	22.86 MHz
64 TOSC	110	48.0 MHz	45.71 MHz
RC(3)	x11	1.00 MHz(1)	1.00 MHz(2)

Note 1: The RC source has a typical TAD time of 4 ms.

2: The RC source has a typical TAD time of 6 ms.

3: For device frequencies above 1 MHz, the device must be in Sleep for the entire conversion or the A/D accuracy may be out of specification.

4: Low-power devices only.

Disposable / Reusable Dry EEG Electrode [TDE-200]

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This disposable/reusable Dry EEG Electrode can also be used for other parameters such as EMG, ECG or EOG. It is used with the TDE-207XX Lead Wire.

Diameter at the bottom is 13/32". Top diameter is 1/4".

There is a narrower notch just below the top, for the electrode cable to snap into. That notch is 7/32" in diameter.

Select the quantity from the drop down box.

--

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